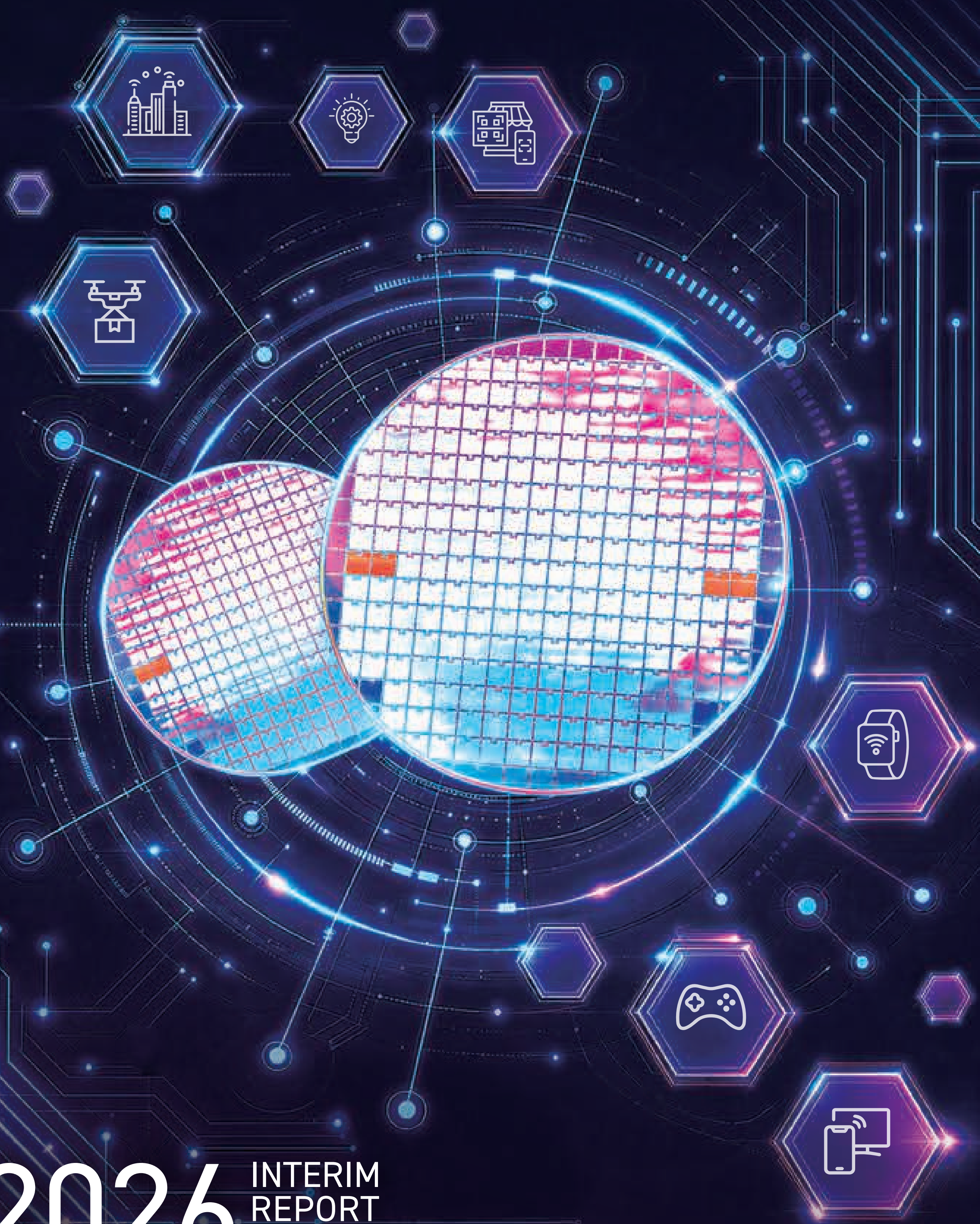
Solomon Systech (International) Limited
晶門半導體有限公司
(Incorporated in Cayman Islands with limited liability)
(於開曼群島註冊成立的有限公司)
Stock Code 股份代號: 2878



2026 INTERIM REPORT
中期報告

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CORPORATE PROFILE
公司簡介

Solomon Systech (International) Limited and its subsidiaries as a group is a leading semiconductor group specialising in the design, development and sales of integrated circuits products and system solutions that enable a wide range of display and touch applications for smartphones, tablets, TVs/monitors, notebooks and other smart devices, including wearables, electronic shelf labels (ESLs), healthcare devices, smart home devices, as well as industrial appliances, etc.

晶門半導體有限公司及其附屬公司為一家具領導地位的半導體集團，專門設計、開發及銷售集成電路晶片產品及系統解決方案，能廣泛應用於智能手機、平板電腦、電視／顯示器、筆記本電腦以及其他智能產品，包括可穿戴產品、電子貨架標籤、醫療保健產品、智能家居產品，以及工業用設備等提供廣泛的顯示及觸控應用。

VISION

Provide the ultimate silicon solution for every display system

願景

為每個顯示系統提供
最終的晶片解決方案

FINANCIAL HIGHLIGHTS
財務摘要

(A) Results 業績		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月		
		2026	2025	
		US$ million 百萬美元	US$ million 百萬美元	Change % 變動百分比
Revenue	銷售額	**43.7**	45.9	-4.8%
Gross profit	毛利	**12.0**	18.2	-34.1%
Gross margin (%)	毛利率(%)	**27.4**	39.6	-12.2 percentage points 百分點
(Loss)/profit attributable to owners of the parent	本公司擁有人應佔（損失）／溢利	**(4.0)**	4.0	
(Loss)/earnings per share (US cent)	每股（損失）／盈利（美仙）	**(0.16)**	0.16	

(B) Financial Position 財務狀況		**Unaudited 未經審核 As at 30 June 6月30日 2026**	Audited 經審核 As at 31 December 12月31日 2025	
		US$ million 百萬美元	US$ million 百萬美元	Change % 變動百分比
Total assets	總資產	**164.1**	164.7	-0.4%
Shareholders' funds	股東權益	**139.2**	141.9	-1.9%

(C) Financial Ratios 財務比率			
(i) Current ratio	流動比率	**6.32**	7.01
(ii) Debt to equity ratio	債務權益比率	**N/A 不適用**	N/A 不適用

Interim Dividend

The Board of Solomon Systech (International) Limited (the "Company") does not recommend the payment of an interim dividend for the six months ended 30 June 2026 (the "Period").

中期股息

晶門半導體有限公司的董事會不建議宣派截至2026年6月30日止6個月的中期股息。

Unaudited Interim Results

The Board is pleased to announce the unaudited condensed consolidated interim results of the Company and its subsidiaries (collectively referred to as the "Group") for the six months ended 30 June 2026 together with the comparative figures for the corresponding period as follows.

未經審核中期業績

董事會欣然宣佈，本公司及其附屬公司（統稱「本集團」）截至2026年6月30日止6個月的未經審核簡明綜合中期業績連同上年度同期的比較數字列載如下。

INTERIM CONDENSED CONSOLIDATED STATEMENT OF PROFIT OR LOSS
中期簡明綜合損益表

For the six months ended 30 June 2026
截至2026年6月30日止6個月

			Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		Notes 附註	**2026** **US$'000** **千美元**	2025 US$'000 千美元
Revenue	**銷售額**	5	**43,723**	45,934
Cost of sales	銷售成本		**(31,742)**	(27,759)
Gross profit	毛利		**11,981**	18,175
Other income and gains – net	其他收入及收益－淨額		**250**	514
Research and development costs	研究及開發成本		**(10,246)**	(9,943)
Selling and distribution expenses	銷售及分銷開支		**(1,712)**	(1,640)
General and administrative expenses	行政及一般開支		**(5,299)**	(5,207)
Foreign exchange differences – net	外滙差額－淨額		**(456)**	81
Other expenses	其他開支		**(23)**	–
			(5,505)	1,980
Finance income – net	投資收入－淨額	7	**1,552**	2,080
			(3,953)	4,060
Share of profits of associates	應佔聯營公司盈利		**–**	44
(Loss)/profit before tax	除税前(損失)/溢利	6	**(3,953)**	4,104
Income tax expense	所得税開支	8	**–**	(101)
(Loss)/profit for the period attributable to owners of the parent	**期內本公司擁有人應佔(損失)/溢利**		**(3,953)**	4,003
(Loss)/earnings per share attributable to ordinary equity holders of the parent: (in US cent)	本公司普通權益持有人應佔的每股(損失)/溢利:(美仙)	9		
– Basic	－ 基本		**(0.16)**	0.16
– Diluted	－ 攤薄		**(0.16)**	0.16

The notes on pages 8 to 26 form an integral part of this interim condensed consolidated financial information.
第8至26頁的附註為本中期簡明綜合財務資料的組成部份。

INTERIM CONDENSED CONSOLIDATED STATEMENT OF COMPREHENSIVE INCOME
中期簡明綜合全面收入表

For the six months ended 30 June 2026
截至2026年6月30日止6個月

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026	2025
		US$'000	US$'000
		千美元	千美元
(Loss)/profit for the period	期內(損失)／溢利	**(3,953)**	4,003
Other comprehensive income	其他全面收益		
Other comprehensive income that may be reclassified to profit or loss in subsequent periods:	於往後期間，其他全面收益將重新分類至損益表：		
– Exchange differences on translation of foreign operations	－ 換算海外業務時之匯兑差額	**1,301**	78
Total comprehensive (loss)/income for the period attributable to owners of the parent	期內本公司擁有人應佔全面(損失)／收益總計	**(2,652)**	4,081

The notes on pages 8 to 26 form an integral part of this interim condensed consolidated financial information.
第8至26頁的附註為本中期簡明綜合財務資料的組成部份。

INTERIM CONDENSED CONSOLIDATED STATEMENT OF FINANCIAL POSITION
中期簡明綜合財務狀況表

As at 30 June 2026
於2026年6月30日

		Notes 附註	**Unaudited 未經審核 30 June 於6月30日 2026 US$'000 千美元**	Audited 經審核 31 December 於12月31日 2025 US$'000 千美元
NON-CURRENT ASSETS	**非流動資產**			
Property, plant and equipment	物業、廠房及設備		**5,710**	6,196
Right-of-use assets	使用權資產		**1,675**	2,237
Investments in associates	於聯營公司的投資		**1,092**	1,092
Financial asset designated at fair value through other comprehensive income	按公平價值計入其他全面收益的金融資產		**1,219**	1,219
Other receivables, prepayments and deposits	其他應收款，預付款及訂金	11	**104**	456
Total non-current assets	非流動資產總計		**9,800**	11,200
CURRENT ASSETS	**流動資產**			
Inventories	存貨		**14,005**	18,294
Trade and other receivables, prepayments and deposits	應收款及其他應收款、預付款項及訂金	11	**29,791**	28,316
Pledged bank deposits	已抵押的銀行存款		**2,500**	2,500
Cash and cash equivalents	現金及現金等價物		**107,982**	104,413
Total current assets	流動資產總計		**154,278**	153,523
CURRENT LIABILITIES	**流動負債**			
Trade and other payables	應付款及其他應付款	12	**22,527**	19,904
Lease liabilities	租賃負債		**1,337**	1,494
Tax payable	應付税款		**537**	514
Total current liabilities	流動負債總計		**24,401**	21,912
NET CURRENT ASSETS	**流動資產淨值**		**129,877**	131,611
TOTAL ASSETS LESS CURRENT LIABILITIES	**總資產減流動負債**		**139,677**	142,811
NON-CURRENT LIABILITIES	**非流動負債**			
Lease liabilities	租賃負債		**454**	936
Total non-current liabilities	非流動負債總計		**454**	936
Net assets	**資產淨值**		**139,223**	141,875
EQUITY	**權益**			
Equity attributable to owners of the parent	**本公司擁有人應佔權益**			
Issued capital	已發行股本	13	**32,193**	32,193
Reserves	儲備		**107,030**	109,682
Total equity	**總權益**		**139,223**	141,875

The notes on pages 8 to 26 form an integral part of this interim condensed consolidated financial information.
第8至26頁的附註為本中期簡明綜合財務資料的組成部份。

INTERIM CONDENSED CONSOLIDATED STATEMENT OF CHANGES IN EQUITY
中期簡明綜合權益變動表

For the six months ended 30 June 2026
截至2026年6月30日止6個月

		Unaudited 未經審核 Attributable to owners of the parent 本公司擁有人應佔								
		Issued capital 已發行股本 US$'000 千美元	Share premium 股份溢價 US$'000 千美元	Merger reserve 合併儲備 US$'000 千美元	Exchange reserve 匯兑儲備 US$'000 千美元	Equity compensation reserve 股本權益報酬儲備 US$'000 千美元	Fair value reserve 公平值儲備 US$'000 千美元	Other reserve 其他儲備 US$'000 千美元	Retained profits 保留溢利 US$'000 千美元	Total equity 總權益 US$'000 千美元
At 1 January 2025	於2025年1月1日	32,193	78,255	2,082	(3,169)	18,216	1,019	230	8,215	137,041
Profit for the period	期內溢利	–	–	–	–	–	–	–	4,003	4,003
Other comprehensive income for the period	期內其他全面收入									
– Exchange differences on translation of foreign operations	– 換算海外業務時產生之匯兑差額	–	–	–	78	–	–	–	–	78
Total comprehensive income	**全面收入總計**	–	–	–	78	–	–	–	4,003	4,081
Equity-settled share option arrangements	股本權益報酬	–	–	–	–	1	–	–	–	1
Transfer of equity compensation reserve upon the cancellation/lapse/forfeiture of share options	因購股權註銷/失效/沒收而引起之股本權益報酬儲備轉移	–	–	–	–	(467)	–	–	467	–
At 30 June 2025	於2025年6月30日	32,193	78,255	2,082	(3,091)	17,750	1,019	230	12,685	141,123
At 1 January 2026	**於2026年1月1日**	**32,193**	**78,255***	**2,082***	**(2,421)***	**14***	**1,077***	**230***	**30,445***	**141,875**
Loss for the period	**期內損失**	**–**	**–**	**–**	**–**	**–**	**–**	**–**	**(3,953)**	**(3,953)**
Other comprehensive income for the period	**期內其他全面收入**									
– Exchange differences on translation of foreign operations	**– 換算海外業務時產生之匯兑差額**	**–**	**–**	**–**	**1,301**	**–**	**–**	**–**	**–**	**1,301**
Total comprehensive income/(loss)	**全面收入/(虧損)總計**	**–**	**–**	**–**	**1,301**	**–**	**–**	**–**	**(3,953)**	**(2,652)**
Transfer of equity compensation reserve upon the cancellation/lapse/forfeiture of share options	**因購股權註銷/失效/沒收而引起之股本權益報酬儲備轉移**	**–**	**–**	**–**	**–**	**(7)**	**–**	**–**	**7**	**–**
At 30 June 2026	**於2026年6月30日**	**32,193**	**78,255***	**2,082***	**(1,120)***	**7***	**1,077***	**230***	**26,499***	**139,223**

The notes on pages 8 to 26 form an integral part of this interim condensed consolidated financial information.
第8至26頁的附註為本中期簡明綜合財務資料的組成部份。

* These reserve accounts comprise the consolidated reserves of US$107,030,000 (31 December 2025: US$109,682,000) in the interim condensed consolidated statement of financial position.

* 該等儲備包括綜合儲備107,030,000美元(2025年12月31日:109,682,000美元)載於中期簡明綜合財務狀況表。

INTERIM CONDENSED CONSOLIDATED STATEMENT OF CASH FLOWS
中期簡明綜合現金流量表

For the six months ended 30 June 2026
截至2026年6月30日止6個月

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月 **2026** **US$'000** **千美元**	 2025 US$'000 千美元
Net cash flows from operating activities	**經營活動產生的現金流量淨額**	**2,382**	7,322
Cash flows from investing activities	**投資活動之現金流量**		
Purchases of items of property, plant and equipment	購置物業、廠房及設備	**(123)**	(1,839)
Placement of pledged bank deposits	存入已抵押銀行存款	**–**	(2,517)
Release of pledged bank deposits	贖回已抵押銀行存款	**–**	2,500
Proceeds from disposal of items of property, plant and equipment	出售物業、廠房及設備所得款項	**16**	–
Interest received	已收利息	**1,607**	2,171
Net cash flows from investing activities	**投資活動產生的現金流量淨額**	**1,500**	315
Cash flows from financing activities	**融資活動之現金流量**		
Principal portion of lease payments	租賃付款的本金部分	**(719)**	(749)
Drawdowns of bank borrowings	支取銀行貸款	**–**	1,323
Net cash flows (used in)/from financing activities	**融資活動(使用)／產生的現金流量淨額**	**(719)**	574
Net increase in cash and cash equivalents	**現金及現金等價物增加**	**3,163**	8,211
Cash and cash equivalents at beginning of period	**期初現金及現金等價物**	**104,413**	104,242
Effect of foreign exchange rate changes, net	匯率變動之影響，淨額	**406**	60
Cash and cash equivalents at end of period	**期末現金及現金等價物**	**107,982**	112,513
Cash and cash equivalents as stated in the interim condensed consolidated statement of financial position	中期簡明綜合財務狀況表所列的現金及現金等價物	**107,982**	112,513

The notes on pages 8 to 26 form an integral part of this interim condensed consolidated financial information.
第8至26頁的附註為本中期簡明綜合財務資料的組成部份。

1. General information

Solomon Systech (International) Limited and its subsidiaries are a fabless semiconductor group specialising in the design, development and sales of integrated circuits ("IC") products and system solutions that enable a wide range of display applications for smartphones, tablets, smart TVs/monitors, notebooks and other smart devices, including electronic shelf-labels ("ESLs"), wearables, healthcare devices, smart home devices, as well as industrial appliances, etc.

The Company was incorporated in the Cayman Islands on 21 November 2003 as an exempted company with limited liability under Cap. 22, the Cayman Islands Companies Law (Law 3 of 1961, as consolidated and revised). The address of its registered office is P.O. Box 31119, Grand Pavilion, Hibiscus Way, 802 West Bay Road, Grand Cayman KY1-1205, Cayman Islands and the address of its principal office in Hong Kong is Unit 607-613, 6/F. Wireless Centre, 3 Science Park East Avenue, Hong Kong Science Park, Shatin, New Territories, Hong Kong.

The Company has been listed on the Main Board of The Stock Exchange of Hong Kong Limited since 8 April 2004. This interim condensed consolidated financial information is presented in US dollars, unless otherwise stated.

The interim condensed consolidated financial information has been reviewed but not audited, and it was approved for issue on 21 August 2026.

1. 一般資料

晶門半導體有限公司及其附屬公司為無晶圓廠半導體集團，專門設計、開發及銷售集成電路晶片產品及系統解決方案，能廣泛應用於智能手機、平板電腦、電視／顯示器、筆記本電腦以及其他智能產品，包括電子貨架標籤，可穿戴產品、醫療保健設備、智能家居設備，以及工業用設備等作各類顯示及觸控應用。

本公司於2003年11月21日根據開曼群島公司法（1961年法律3，經綜合及修訂）第22章在開曼群島註冊成立為一間獲豁免有限公司。本公司註冊辦事處的地址為P.O. Box 31119, Grand Pavilion, Hibiscus Way, 802 West Bay Road, Grand Cayman KY1-1205，開曼群島，而其香港總辦事處的地址為香港新界沙田香港科學園科技大道東3號無線電中心6樓607-613室。

本公司自2004年4月8日起，在香港聯合交易所有限公司主板上市。除另有列明外，本中期簡明綜合財務資料均以美元作呈列單位。

本中期簡明綜合財務資料乃經審閱但未經審核，並於2026年8月21日獲批准刊發。

2. Basis of preparation

The interim condensed consolidated financial information for the six months ended 30 June 2026 (the "Period") of the Group has been prepared in accordance with HKAS 34 *Interim Financial Reporting* as issued by the Hong Kong Institute of Certified Public Accountants. The interim condensed consolidated financial information does not include all the information and disclosures required in the annual financial statements, and should be read in conjunction with the Group's annual consolidated financial statements for the year ended 31 December 2025.

2. 編製基準

本集團截至2026年6月30日止6個月的中期簡明綜合財務資料已根據香港會計師公會頒佈的香港會計準則第34號「中期財務報告」編製。中期簡明綜合財務資料並沒有載有一般收錄於年度綜合財務報表之所有資料及附註，故此，應與本集團截至2025年12月31日止年度的綜合財務報表一併閱讀。

3. Changes in Accounting Policies

The accounting policies adopted in the preparation of the interim condensed consolidated financial information are consistent with those applied in the preparation of the Group's annual consolidated financial statements for the year ended 31 December 2025, except for the adoption of the following amended HKFRS Accounting Standards for the first time for the current period's financial information.

3. 會計政策變動

編製本中期簡明綜合財務資料時採用的會計政策與編製截至2025年12月31日止年度的本集團年度綜合財務報表時採用的會計政策一致，但本期財務資料首次採用以下經修訂香港財務報告會計準則。

Amendments to HKFRS 9 and HKFRS 7 香港財務報告準則第9號及香港財務報告準則第7號之修訂	*Amendments to the Classification and Measurement of Financial Instruments* *金融工具分類與計量之修訂*
Amendments to HKFRS 9 and HKFRS 7 香港財務報告準則第9號及香港財務報告準則第7號之修訂	*Contracts Referencing Nature-dependent Electricity* *涉及依賴自然能源生產電力的合約*
Annual Improvements to HKFRS Accounting Standards – Volume 11 *香港財務報告會計準則之年度改進 — 第11冊*	Amendments to HKFRS 1, HKFRS 7, HKFRS 9, HKFRS 10 and HKAS 7 香港財務報告準則第1號、香港財務報告準則第7號、香港財務報告準則第9號、香港財務報告準則第10號及香港會計準則第7號之修訂

3. Changes in Accounting Policies (continued)

The nature and impact of the amended HKFRS Accounting Standards are described below:

(a) Amendments to HKFRS 9 and HKFRS 7 *Amendments to the Classification and Measurement of Financial Instruments* clarify that a financial asset is derecognised when the entity's rights to the contractual cash flows expire or are transferred, while a financial liability is derecognised on the settlement date. The amendments introduce an accounting policy option to derecognise a financial liability that is settled through an electronic payment system before the settlement date if specified criteria are met. The amendments clarify how to assess the contractual cash flow characteristics of financial assets with environmental, social and governance and other similar contingent features. Moreover, the amendments clarify the requirements for classifying financial assets with non-recourse features and contractually linked instruments. The amendments also include additional disclosures for investments in equity instruments designated at fair value through other comprehensive income and financial instruments with contingent features.

Prior to the initial application of the amendments, the Group derecognised trade payables that were settled by cheques upon the issuance of cheques to creditors. Upon applying the amendments, trade payables that were settled by cheques are derecognised on the settlement date which is the date when the cheques are cleared by banks. The change in accounting policy did not have a material impact on the Group's interim condensed consolidated financial information. The change in accounting policy will be reflected in the Group's consolidated financial statements for the year ending 31 December 2026.

3. 會計政策變動(續)

經修訂香港財務報告會計準則的性質及影響說明如下：

(a) 香港財務報告準則第9號及香港財務報告準則第7號之修訂*金融工具分類與計量之修訂*澄清當實體對合約現金流量的權利屆滿或被轉讓時，金融資產予以終止確認，而金融負債則於結算日期終止確認。該等修訂引入一項會計政策選擇，在達致特定標準的情況下，終止確認於結算日期之前通過電子支付系統結算的金融負債。該等修訂澄清如何評估具有環境、社會及管治以及其他類似或然特性的金融資產的合約現金流特性。此外，該等修訂澄清對具有無追索權特性的金融資產及合約掛鉤工具進行分類的規定。該等修訂亦包括對指定為按公平價值計入其他全面收益的股權工具及具有或然特性的金融工具之投資的額外披露規定。

在首次應用該等修訂前，本集團向債權人開立支票時，會終止確認以支票結算的應付款。應用該等修訂後，以支票結算的應付款將於結算日期(即銀行清算支票當日)終止確認。該會計政策變動對本集團中期簡明綜合財務資料並無重大影響。該會計政策變動將反映於本集團截至2026年12月31日止年度的綜合財務報表。

3. Changes in Accounting Policies (continued)

(b) Amendments to HKFRS 9 and HKFRS 7 *Contracts Referencing Nature-dependent Electricity* clarify the application of the "own-use" requirements for in-scope contracts and amend the designation requirements for a hedged item in a cash flow hedging relationship for in-scope contracts. The amendments also include additional disclosures that enable users of financial statements to understand the effects these contracts have on an entity's financial performance and future cash flows. As the Group did not have any contracts that are in the scope of the amendments, the amendments did not have any impact on the interim condensed consolidated financial information.

(c) *Annual Improvements to HKFRS Accounting Standards – Volume 11* set out narrow scope amendments to HKFRS 1, HKFRS 7 (and the accompanying *Guidance on implementing HKFRS 7*), HKFRS 9, HKFRS 10 and HKAS 7. The amendments include clarifications, simplifications, corrections or changes to improve consistency in the corresponding HKFRS Accounting Standards. The amendments did not have any impact on the interim condensed consolidated financial information.

3. 會計政策變動(續)

(b) 香港財務報告準則第9號及香港財務報告準則第7號之修訂*涉及依賴自然能源生產電力的合約*澄清範圍內合約「自用」規定的應用，並修訂範圍內合約現金流量對沖關係中指定的被對沖項目的規定。該等修訂本亦包括額外披露，使財務報表使用者能夠了解該等合約對實體財務表現及未來現金流量的影響。由於本集團並無任何合約屬於該等修訂的適用範圍，因此該等修訂對中期簡明綜合財務資料並無任何影響。

(c) *香港財務報告會計準則之年度改進－第11冊*載列香港財務報告準則第1號、香港財務報告準則第7號(及隨附的*實施香港財務報告準則第7號指引*)、香港財務報告準則第9號、香港財務報告準則第10號及香港會計準則第7號所作出的範圍有限的修訂。該等修訂包括為提高相關香港財務報告會計準則的一致性而作出的澄清、簡化、更正或變更。該等修訂對中期簡明綜合財務資料並無任何影響。

4. Fair value and fair value hierarchy of financial instruments

The carrying amount and fair value of the Group's financial instruments, other than those with carrying amounts that reasonably approximate to fair values, are as follows:

4. 金融工具之公平值及公平價值級別

除賬面值合理地接近公平值的金融工具外，本集團金融工具的賬面值和公平值如下：

		Carrying amount 賬面值		Fair value 公平值	
		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元	**Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元**	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Financial asset	**金融資產**				
Financial asset designated at fair value through other comprehensive income	按公平價值計入其他全面收入的金融資產	**1,219**	1,219	**1,219**	1,219

Management has assessed that the fair values of cash and cash equivalents, pledged bank deposits, trade receivables, trade payables, the current portion of financial assets included in deposits and other receivables, and financial liabilities included in other payables approximate to their carrying amounts largely due to the short term maturities of these instruments.

管理層已評估現金及現金等價物、已抵押銀行存款、應收款、應付款及應付票據、包括在流動部份的訂金及其他應收款中的金融資產、包括在其他應付款及應計項目中的金融負債及流動部份的租賃負債的公平價值與其賬面金額相近，主要是由於這些工具於短時間內到期。

The fair values of the financial assets and liabilities are included at the amount at which the instrument could be exchanged in a current transaction between willing parties, other than in a forced or liquidation sale.

金融資產及負債的公平價值按自願交易方(而非強迫或清盤銷售)於當前交易中交換該工具的金額入賬。

4. Fair value and fair value hierarchy of financial instruments (continued)

4. 金融工具之公允值及公允價值級別(續)

The following methods and assumptions were used to estimate the fair values:

以下方法和假設用於估計公平價值：

The fair value of an unlisted financial asset designated at fair value through other comprehensive income is estimated by observable prices of similar assets. The directors believe that the estimated fair value, which is recorded in the interim condensed consolidated statement of financial position, and the related changes in fair value, which are recorded in other comprehensive income, are reasonable, and that it was the most appropriate value at the end of the reporting period.

以按公允價值計入其他全面收入的非上市金融資產的公允價值乃按可觀察價格或類似資產的銷售率估算。董事認為，綜合財務狀況表中記錄的估計公允價值以及公允價值的相關變動(記入其他全面收益)是合理的，並且它是報告期末最合適的價值。

The following table illustrates the fair value measurement hierarchy of the Group's financial instrument measured at fair value:

下表説明了本集團金融工具的公允價值計量級別：

Asset measured at fair value:

資產按公平值計量：

As at 30 June 2026

於2026年6月30日

		Fair value measurement using 公平值計量利用			
		Quoted prices in active markets 於活躍市場報價 (Level 1) (第1層級) US$'000 千美元 (Unaudited) (未經審核)	Significant observable inputs 可觀察輸入數據 (Level 2) (第2層級) US$'000 千美元 (Unaudited) (未經審核)	Significant unobservable inputs 不可觀察輸入數據 (Level 3) (第3層級) US$'000 千美元 (Unaudited) (未經審核)	Total 總計 US$'000 千美元 (Unaudited) (未經審核)
Financial asset designated at fair value through other comprehensive income	按公平價值計入其他全面收入的金融資產	–	1,219	–	1,219

4. Fair value and fair value hierarchy of financial instruments (continued)

Asset measured at fair value: (continued)

As at 31 December 2025

4. 金融工具之公平值及公平價值級別(續)

資產按公平值計量:(續)

於2025年12月31日

		Fair value measurement using 公平值計量利用			
		Quoted prices in active markets 於活躍市場報價 (Level 1) (第1層級) US$'000 千美元 (Audited) (經審核)	Significant observable inputs 可觀察輸入數據 (Level 2) (第2層級) US$'000 千美元 (Audited) (經審核)	Significant unobservable inputs 不可觀察輸入數據 (Level 3) (第3層級) US$'000 千美元 (Audited) (經審核)	Total 總計 US$'000 千美元 (Audited) (經審核)
Financial asset designated at fair value through other comprehensive income	按公平價值計入其他全面收入的金融資產	–	1,219	–	1,219

During the six months ended 30 June 2026, there were no transfers of fair value measurements between Level 1 and Level 2 and no transfers into or out of Level 3 for financial assets (1H 2025: Nil).

截至2026年6月30日止6個月,第1層級及第2層級之間沒有公平值計量轉移,沒有第3層級金融資產轉入或轉出(2025年上半年:無)。

The Group did not have any financial liabilities measured at fair value as at 30 June 2026 and 31 December 2025.

於2026年6月30日及2025年12月31日,本集團沒有金融負債以公平值計量。

5. Segment information and disaggregation of revenue

The Group is principally engaged in the design, development and sales of proprietary IC products and system solutions that enable a wide range of display and touch applications for smartphones, tablets, smart TVs/monitors, notebooks and other smart devices, including electronic shelf-labels (ESLs), wearables, healthcare devices, smart home devices, as well as industrial appliances, etc.

The Group has been operating in one single operating segment, i.e., the design, development and sales of IC products and system solutions.

5. 分部資料及銷售額分類

本集團主要從事設計、開發、銷售專有IC產品及系統解決方案,能廣泛應用於智能手機、平板電腦、電視/顯示器、筆記本電腦以及其他智能產品,包括電子貨架標籤,可穿戴產品、醫療保健設備、智能家居設備,以及工業用設備等作各類顯示及觸控應用。

本集團一直以單一營運分部經營,即設計、開發及銷售專有IC產品及系統解決方案。

5. Segment information and disaggregation of revenue (continued)

The chief operating decision-makers have been identified as the Executive Director and senior management led by the Chief Executive Officer. The Executive Director and senior management reviewed the Group's internal reporting as a whole to assess performance and allocate resources.

Sales amounted to US$43,723,000 for the six months ended 30 June 2026 (1H 2025: US$45,934,000).

The Group mainly operates in Hong Kong. During the Period under review, the Group's products were mainly sold to customers located in Hong Kong, Europe and Taiwan.

5. 分部資料及銷售額分類(續)

本集團最高營運決策層為本集團行政總裁暨領導下的執行董事和高級管理層。執行董事和高級管理層檢討本集團內部報告以評估業績及分配資源。管理層基於該等報告確定營運分部報告。

截至2026年6月30日止6個月,銷售額為43,723,000美元(2025年上半年:45,934,000美元)。

本集團主要於香港經營其業務。於回顧期內,本集團之產品主要銷售予位於香港、歐洲及台灣的客戶。

(a) Revenue from contracts with customers disaggregated by geographical market

(a) 按地域市場分類的客戶合約收益

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026	2025
		US$'000	US$'000
		千美元	千美元
Hong Kong	香港	**24,908**	28,033
Europe	歐洲	**6,282**	7,243
Taiwan	台灣	**7,184**	7,029
Japan	日本	**2,138**	2,316
Mainland China	中國內地	**3,033**	1,142
Korea	韓國	**119**	66
South East Asia	東南亞	**4**	21
USA	美國	**1**	–
Others	其他	**54**	84
		43,723	45,934

Sales are classified based on the places/countries in which customers are located.

銷售額按客戶所在地區/國家分類。

5. Segment information and disaggregation of revenue (continued)

5. 分部資料及銷售額分類(續)

(b) Revenue from contracts with customers disaggregated by product types

(b) 按產品種類分類的客戶合約收益

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026	2025
		US$'000	US$'000
		千美元	千美元
New Display ICs	新型顯示ICs	**28,149**	29,621
OLED Display ICs	OLED顯示ICs	**7,738**	7,270
Mobile Display and Mobile Touch ICs	移動顯示及移動觸控ICs	**4,046**	5,879
Large Display ICs	大型顯示ICs	**3,790**	3,164
		43,723	45,934

(c) Non-current assets

(c) 非流動資產

		Unaudited	Audited
		未經審核	經審核
		30 June	31 December
		6月30日	12月31日
		2026	2025
		US$'000	US$'000
		千美元	千美元
Hong Kong	香港	**1,245**	1,638
Mainland China	中國內地	**5,719**	6,283
Taiwan	台灣	**1,513**	1,604
		8,477	9,525

The non-current asset information above is based on the locations of the assets and excludes financial assets.

非流動資產(不包含金融資產)乃根據資產的所在地予以列載。

(d) Capital expenditures

(d) 資本開支

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026	2025
		US$'000	US$'000
		千美元	千美元
Property, plant and equipment	**物業、廠房及設備**		
Mainland China	中國內地	**14**	1,777
Hong Kong	香港	**109**	47
Taiwan	台灣	**–**	15
		123	1,839

Capital expenditures are listed based on the locations of assets.

資本開支是根據資產的所在地予以列載。

5. Segment information and disaggregation of revenue (continued)

(e) Major customers

For the six months ended 30 June 2026, the largest and second largest customers were located in Hong Kong and Europe, respectively. Sales to those customers were US$21,880,000 and US$4,582,000, respectively, which individually accounted for over 10% of the Group's total revenue. For the six months ended 30 June 2025, the largest and second largest customers were located in Hong Kong and Europe, respectively. Sales to those customers were US$23,872,000 and US$5,912,000, respectively, which individually accounted for over 10% of the Group's total revenue.

5. 分部資料及銷售額分類（續）

(e) 主要客戶

截至2026年6月30日止6個月，最大及第二大客戶分別位於香港及歐洲。其銷售額分別為21,880,000美元及4,582,000美元，並各佔本集團總銷售額超過10%。截至2025年6月30日止6個月，最大及第二大客戶分別位於香港及歐洲。其銷售額為23,872,000美元及5,912,000美元，並各佔本集團總銷售額超過10%。

6. (Loss)/profit before tax

The Group's (loss)/profit before tax is arrived at after charging/(crediting):

6. 除稅前（損失）╱溢利

本集團的除稅前（損失）╱溢利乃扣除╱（計入）下列各項後得出：

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月 2026 US$'000 千美元	2025 US$'000 千美元
Cost of inventories sold	銷貨成本	**31,227**	29,521
Provision/(reversal of provision) for obsolete or slow-moving inventories, net	過時或滯銷存貨的撥備╱（撥備回撥）淨額	**41**	(2,213)
Depreciation of property, plant and equipment (note 1)	物業廠房設備折舊（附註一）	**788**	816
Depreciation of right-of-use assets (note 2)	使用權資產折舊（附註二）	**650**	699
Impairment of trade receivables	應收款減值撥備	**26**	–
Reversal of impairment of other receivables and deposits	其他預付款項及訂金撥備回撥	**(3)**	–
Gain on disposal of items of property, plant and equipment	出售物業、廠房及設備項目的收益	**(16)**	–

Note 1: Depreciation expense of US$410,000 (1H 2025: US$389,000) has been charged in cost of sales, US$42,000 (1H 2025: US$53,000) in research and development costs and US$336,000 (1H 2025: US$374,000) in administrative expenses.

Note 2: Depreciation of right-of-use assets of US$64,000 (2025 1H: US$62,000) is included in "Cost of sales" in the interim condensed consolidated statement of profit or loss.

附註一： 折舊開支410,000美元（2025年上半年：389,000美元）已於銷售成本中支銷，而42,000美元（2025年上半年：53,000美元）則於研究及開發成本中入賬及336,000美元（2025年上半年：374,000美元）於行政開支中入賬。

附註二： 使用權資產折舊64,000美元（2025上半年：62,000美元）已計入中期簡明綜合損益表內銷售成本。

7. Finance income – net

7. 投資收入－淨額

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026 **US$'000** **千美元**	2025 US$'000 千美元
Interest income	利息收入	**1,607**	2,171
Interest on bank loans	銀行貸款的利息支出	**–**	(5)
Interest on lease liabilities	租賃負債的利息支出	**(55)**	(86)
		1,552	2,080

8. Income tax

No provision for Hong Kong profits tax has been made for the current period as the Group has no estimated assessable profits arising in Hong Kong for the period. In the prior period, no provision for Hong Kong profits tax was made as the Group had available tax losses brought forward from previous years to offset the assessable profits generated in the prior period. Taxes on profits assessable elsewhere have been calculated at the rates of tax prevailing in the jurisdictions in which the Group operates.

8. 所得稅

本集團於香港概無評稅利潤，概無作本期間香港所得稅撥備。於往年本集團因有承前自以往年度之可動用稅務虧損可用以抵銷期內香港產生之應課稅溢利，因此並無作本期間香港利得稅撥備。海外所得稅則根據本集團的營運所在司法權區之適用稅率計算。

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026 **US$'000** **千美元**	2025 US$'000 千美元
Current – Elsewhere – income tax – Charge for the period	即期－其他地區 －本期支出	**–**	101
Total tax charge for the period	本期所得稅開支總額	**–**	101

9. (Loss)/earnings per share

(a) Basic (loss)/earnings per share

The basic (loss)/earnings per share is calculated based on the Group's (loss)/profit for the Period attributable to owners of the parent and the weighted average number of ordinary shares of 2,497,752,351 (1H 2025: 2,497,752,351) outstanding during the period.

The Group's loss for the Period attributable to owners of the parent was US$3,953,000 (1H 2025: Profit of US$4,003,000).

9. 每股(損失)／盈利

(a) 每股基本(損失)／盈利

每股基本(損失)／盈利是根據本公司的擁有人應佔本集團之(損失)／溢利及本期內已發行普通股加權平均數2,497,752,351股(2025上半年：2,497,752,351股)計算。

本公司的擁有人期內應佔本集團之損失為3,953,000美元(2025上半年：溢利4,003,000美元)。

9. (Loss)/earnings per share (continued)

(b) Diluted (loss)/earnings per share

The diluted (loss)/earnings per share is calculated based on the Group's (loss)/profit attributable to owners of the parent and the weighted average number of ordinary shares outstanding after adjusting for the effects of all dilutive potential ordinary shares during the period.

The information related to the weighted average number of ordinary shares is as follows:

9. 每股（損失）╱盈利（續）

(b) 每股攤薄（損失）╱盈利

每股攤薄（損失）╱盈利乃根據本公司的擁有人應佔本集團之（損失）╱溢利及已就期內所有具潛在攤薄影響的普通股作出調整後之已發行加權平均普通股數計算。

加權平均普通股股數的有關資料列載如下：

		Number of shares 股份數目 Unaudited 未經審核 Six months ended 30 June 6月30日止6個月	
		2026	2025
Weighted average number of ordinary shares outstanding	已發行加權平均普通股股數	**2,497,752,351**	2,497,752,351
Conversion of all dilutive share options outstanding (i)	兌換所有可予發行具攤薄影響的流通購股權(i)	**–**	–
Adjusted weighted average number of ordinary shares for diluted (loss)/earnings per share calculation	用作計算每股攤薄（損失）╱盈利的調整後加權平均普通股股數	**2,497,752,351**	2,497,752,351

(i) No adjustment has been made for the six months ended 30 June 2026 as there is no dilutive effect on the 250,000 share options (six months ended 30 June 2025: 500,000 share options) outstanding for the weighted average number of ordinary shares.

(i) 於2026年6月30日止之250,000份（截至2025年6月30日止：500,000份）尚未行使的購股權並未進行攤薄調整，因該等購股權並無攤薄效應。

10. Dividend

The board of directors of the Company resolved not to declare an interim dividend for the six months ended 30 June 2026 (six months ended 30 June 2025: Nil).

10. 股息

董事會亦決議不宣派截至2026年6月30日止6個月的中期股息（截至2025年6月30日止6個月：無）。

11. Trade and other receivables, prepayments and deposits

11. 應收款及其他應收款、預付款項及訂金

		Note 附註	Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Trade receivables	應收款		9,486	9,605
Trade receivables from related parties	關聯方應收款	16(a)	10,894	13,806
Impairment	減值撥備		(241)	(215)
Trade receivables – net	應收款－淨額		20,139	23,196
Other receivables, prepayments and deposits	其他應收款、預付款項及訂金		9,561	4,906
Prepayments to related parties	關聯方預付款	16(a)	100	226
Impairment	減值撥備		(9)	(12)
Trade and other receivables, prepayments and deposits – current portion	應收款及其他應收款、預付款項及訂金－流動		29,791	28,316
Other receivables, prepayments and deposits – non-current portion	其他應收款、預付款項及訂金－非流動		104	456
			29,895	28,772

As at 30 June 2026, the Group's trade receivables from corporate customers were mainly on credit terms of 30 to 90 days. The ageing analysis of the trade receivables as at the end of the reporting period, based on invoice date and net of loss allowance, is as follows:

於2026年6月30日，本集團對企業客戶之應收款信貸期主要為30至90日。應收款以發票日期及扣除減值撥備的賬齡分析如下：

		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
1–30 days	1–30日	11,628	14,675
31–60 days	31–60日	4,236	3,598
61–90 days	61–90日	2,143	4,022
91–180 days	91–180日	297	670
181–360 days	181–360日	1,835	–
Over 360 days	超過360日	–	231
		20,139	23,196

11. Trade and other receivables, prepayments and deposits (continued)

11. 應收款及其他應收款、預付款項及訂金（續）

The movements in the loss allowance for impairment of trade receivables are as follows:

應收款減值撥備變動如下：

		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
At beginning of period/year	於期初／年初	**215**	201
Impairment losses	減值	**26**	14
At end of period/year	於期末／年末	**241**	215

12. Trade and other payables

12. 應付款及其他應付款

		Note 附註	Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Trade payables	應付款		**6,848**	5,973
Trade payables to a related party	關聯方應付款	16(a)	**71**	3
			6,919	5,976
Accrued expenses and other payables	應計開支及其他應付款		**13,472**	11,941
Contract liabilities	合約負債		**716**	621
Refund liabilities	退款負債		**1,420**	1,366
			22,527	19,904

As at 30 June 2026, the ageing analysis of trade payables based on invoice date is as follows:

於2026年6月30日，應付款以發票日期的賬齡分析如下：

		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
1–30 days	1–30日	**3,757**	2,875
31–60 days	31–60日	**1,991**	1,457
61–90 days	61–90日	**718**	1,028
Over 90 days	超過90日	**453**	616
		6,919	5,976

13. Issued capital

13. 已發行股本

		Unaudited 未經審核 30 June 6月30日 2026 Number of shares 股份數目	US$'000 千美元	Audited 經審核 31 December 12月31日 2025 Number of shares 股份數目	US$'000 千美元
Authorised: – Ordinary shares of HK$0.10 each	法定： －每股面值0.10港元的普通股	**5,000,000,000**	**64,433**	5,000,000,000	64,433
Issued and fully paid: At 1 January and at end of period/year	已發行及繳足： 於1月1日及於期末／年末	**2,497,752,351**	**32,193**	2,497,752,351	32,193

14. Equity compensation scheme

The Share Option Scheme

The Company adopted a share option scheme (the "2013 Share Option Scheme") at the annual general meeting held on 28 May 2013.

The following share options under the 2013 Share Option Scheme were outstanding during the Period/year:

14. 股本權益報酬計劃

購股權計劃

本公司於2013年5月28日舉行的股東週年大會已採納一購股權計劃(「2013購股權計劃」)。

期內／年內，2013購股權計劃尚未行使購股權數目如下：

		Unaudited 未經審核 30 June 6月30日 2026 Weighted average exercise price 加權平均行使價 HK$ 港元	Number of options 購股權數目	Audited 經審核 31 December 12月31日 2025 Weighted average exercise price 加權平均行使價 HK$ 港元	Number of options 購股權數目
At beginning of the period/year	於期初／年初	**0.55**	**500,000**	0.62	16,180,000
Lapsed/forfeited during the period/year	期內／年內已註銷／放棄	**0.55**	**(250,000)**	0.62	(15,680,000)
At end of the period/year	於期末／年末	**0.55**	**250,000**	0.55	500,000

14. Equity compensation scheme (continued)

The Share Option Scheme (continued)

During the Period, movements in the number of share options outstanding under the 2013 Share Option Scheme and their related exercise prices are as follows:

14. 股本權益報酬計劃（續）

購股權計劃（續）

期內，關於2013購股權計劃尚未行使購股權數目的變動及其有關行使價列載如下：

		Unaudited 未經審核 Number of share options (in thousand units) 購股權數目（以千位計）						
Grant date 授出日期	Exercise price per share HK$ 每股行使價 港元	Held on 1 January 2026 於2026年1月1日 持有	Granted during the Period 期內已授出	Exercised during the Period 期內已行使	Lapsed/ forfeited during the Period 期內已 註銷／放棄	Held on 30 June 2026 於2026年6月30日 持有	Vesting period 歸屬期	Exercise period 行使期
24 March 2023 2023年3月24日	0.546	**250**	**–**	**–**	**(250)**	**–**	24 March 2023 to 24 March 2024 2023年3月24日至 2024年3月24日	25 March 2024 to 24 March 2026 2024年3月25日至 2026年3月24日
	0.546	**250**	**–**	**–**	**–**	**250**	24 March 2023 to 24 March 2025 2023年3月24日至 2025年3月24日	25 March 2025 to 24 March 2027 2025年3月25日至 2027年3月24日
Total 總計		**500**	**–**	**–**	**(250)**	**250**		

At the end of the reporting period, the total number of share options which are exercisable under the 2013 Share Option Scheme was 250,000 (31 December 2025: 500,000).

於報告期末，根據2013購股權計劃可行使的購股權總數為250,000份（2025年12月31日：500,000份）。

At the end of the reporting period, the Company had 250,000 share options outstanding under the 2013 Share Option Scheme. The exercise in full of the outstanding share options would, under the present capital structure of the Company, result in the issue of 250,000 additional ordinary shares of the Company and additional share capital and share premium in the aggregate of approximately US$18,000 (before issue expenses).

於報告期末，本公司根據該2013購股權計劃尚未行使250,000份購股權。根據本公司現有資本架構，全數行使未行使購股權將導致發行250,000本公司普通股及額外股本連同股份溢價總額約18,000美元（扣除發行費用前）。

15. Capital commitments

The Group had the following contractual commitments at the end of the reporting period:

15. 資本承擔

於報告期末已商定合約列載如下：

		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Property, plant and equipment	物業、廠房及設備	**1,692**	2,156

16. Related party transactions

(a) China Electronics Corporation ("CEC"), a state-owned information technology conglomerate under the administration of the central government of the PRC, through one of its wholly-owned subsidiary, Huada Semiconductor Co. Ltd., owns approximately 28.3% of the issued shares of the Company and is thus a substantial shareholder of the Company. Transactions between the Group and the subsidiaries or associates of CEC are regarded as transactions with related parties.

The following transactions were carried out with related parties:

16. 關聯方交易

(a) 中國電子信息產業集團有限公司(「中國電子」)是直接隸屬於中國中央政府管理的國有電子信息技術企業集團，通過其附屬公司華大半導體有限公司擁有約28.3%本公司之發行股份，乃本公司之主要股東。本集團與中國電子的附屬公司或其聯繫人的交易構成關聯方交易。

以下交易為關聯方之交易：

		Notes 附註	Unaudited 未經審核 Six months ended 30 June 6月30日止6個月 2026 US$'000 千美元	 2025 US$'000 千美元
Sales:	銷售額：			
Subsidiary of CEC	中國電子的附屬公司	(i)	**21,880**	23,872
Testing service fees:	測試服務費：			
Associate of CEC	中國電子的聯營公司	(ii)	**192**	198
Rental service charges:	租賃服務費：			
Subsidiary of CEC	中國電子的附屬公司	(iii)	**13**	15
Software and IT service charges:	軟件及信息技術服務費：			
Subsidiaries of CEC	中國電子的附屬公司	(iv)	**134**	131

16. Related party transactions (continued)

(a) (continued)

Notes:

(i) This represented the transaction amount for the supply of IC and driver products ("**IC Products**") from the Group to CEAC International Limited ("**CEACI**") during the six months ended 30 June 2026, based on the agreement dated 22 October 2020 (the "**IC Products Supply Agreement**"), as subsequently amended on 23 March 2021 and 6 May 2022 entered into between the Company and CEACI. The IC Products Supply Agreement had a term of three years from 1 January 2021 to 31 December 2023. As the IC Products Supply Agreement expired on 31 December 2023, and the Company intended to continue carrying out the existing arrangements with CEACI under the IC Products Supply Agreement for the sales and distribution of the IC Products within the territory as part of the Group's usual and ordinary course of business, the Group entered into a renewed IC Products Supply Agreement with CEACI on 14 November 2023 to renew the arrangements under the IC Products Supply Agreement for a term of three years from 1 January 2024 to 31 December 2026. The IC Products supply transactions contemplated under the IC Products Supply Agreement constituted non-exempt continuing connected transactions for the Company under the Listing Rules and the Company has complied with the relevant requirements under the Listing Rules in respect of such non-exempt continuing connected transactions.

(ii) This represented the testing service fees charged to the Group by an associate of CEC which constituted a continuing connected transaction. The transactions contemplated are subject to reporting, announcement and annual review requirements under the Listing Rules.

(iii) This represented the rental service charges from a subsidiary of CEC to the Group which constituted a fully exempt continuing connected transaction under the Listing Rules.

(iv) This represented the software and IT services charges from subsidiaries of CEC to the Group which constituted fully exempt continuing connected transactions under the Listing Rules.

16. 關聯方交易(續)

(a) (續)

附註：

(i) 這代表根據本公司與中國電子器材國際有限公司(「**CEACI**」)所訂立日期為2020年10月22日的協議(「**IC產品供應協議**」)及其後於2021年3月23日及2022年5月6日修訂，本集團於截至2026年6月30日止六個月向CEACI供應IC及驅動器產品(「**IC產品**」)的交易金額。IC產品供應協議的期限為三年，由2021年1月1日至2023年12月31日。由於IC產品供應協議於2023年12月31日屆滿，而本公司擬於本集團日常及一般業務過程中，繼續根據IC產品供應協議與CEACI進行有關於區域內銷售及分銷IC產品的現有安排，故本集團與CEACI於2023年11月14日訂立IC產品供應協議，以將IC產品供應協議的安排由2024年1月1日起至2026年12月31日止重續三年。IC產品供應協議項下擬進行的IC產品供應交易構成上市規則項下本公司的非豁免持續關連交易，而本公司已就該等非豁免持續關連交易遵守上市規則的相關規定。

(ii) 這代表CEC的一家聯營公司向本集團收取的測試服務費。有關交易構成上市規則項下須遵守申報、公告及年度審核規定。

(iii) 這代表CEC的一家附屬公司向本集團收取的租賃服務費，有關交易構成上市規則項下的全面豁免持續關連交易。

(iv) 這代表中國電子的附屬公司向本集團收取的軟件及信息技術服務費，有關交易構成上市規則項下的全面豁免持續關連交易。

16. Related party transactions (continued)

(a) (continued)
Outstanding balances arising from sales/purchases:

16. 關聯方交易(續)

(a) (續)
由銷售／採購構成的未償還帳目：

		Notes 附註	Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Trade receivables:	應收款：			
Subsidiary of CEC	中國電子的附屬公司	11	**10,894**	13,806
Trade payables:	應付款：			
Associate of CEC	中國電子的聯繫人	12	**71**	3
Prepayments:	預付款：			
Subsidiaries of CEC	中國電子的附屬公司	11	**100**	226

(b) Compensation of key management personnel of the Group:

(b) 本集團主要管理人員的報酬：

		Unaudited 未經審核 Six months ended 30 June 6月30日止6個月 2026 US$'000 千美元	2025 US$'000 千美元
Short-term employee benefits	短期僱員福利	**610**	1,191
Post-employment benefits	其他僱員福利	**21**	22
Share-based payment expense	股權開支	**–**	1
Total compensation paid to key management personnel	已付主要管理人員之報酬總額	**631**	1,214

Note: The transactions in respect of the compensation of key management personnel of the Group were exempted continuing connected transactions under the Listing Rules.

附註：有關本集團主要管理人員報酬的交易是上市規則項下的獲豁免持續關連交易。

安永

To the Board of Directors of Solomon Systech (International) Limited
(Incorporated in the Cayman Islands with limited liability)

Introduction

We have reviewed the interim financial information set out on pages 3 to 26, which comprises the condensed consolidated statement of financial position of Solomon Systech (International) Limited (the "Company") and its subsidiaries (the "Group") as at 30 June 2026 and the related condensed consolidated statements of profit or loss, comprehensive income, changes in equity and cash flows for the six-month period then ended, and explanatory notes. The Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited require the preparation of a report on interim financial information to be in compliance with the relevant provisions thereof and Hong Kong Accounting Standard 34 *Interim Financial Reporting* ("HKAS 34") as issued by the Hong Kong Institute of Certified Public Accountants ("HKICPA"). The directors of the Company are responsible for the preparation and presentation of this interim financial information in accordance with HKAS 34. Our responsibility is to express a conclusion on this interim financial information based on our review. Our report is made solely to you, as a body, in accordance with our agreed terms of engagement, and for no other purpose. We do not assume responsibility towards or accept liability to any other person for the contents of this report.

Scope of Review

We conducted our review in accordance with Hong Kong Standard on Review Engagements 2410 *Review of Interim Financial Information Performed by the Independent Auditor of the Entity* as issued by the HKICPA. A review of interim financial information consists of making inquiries, primarily of persons responsible for financial and accounting matters, and applying analytical and other review procedures. A review is substantially less in scope than an audit conducted in accordance with Hong Kong Standards on Auditing and consequently does not enable us to obtain assurance that we would become aware of all significant matters that might be identified in an audit. Accordingly, we do not express an audit opinion.

Conclusion

Based on our review, nothing has come to our attention that causes us to believe that the interim financial information is not prepared, in all material respects, in accordance with HKAS 34.

Ernst & Young
Certified Public Accountants

27/F, One Taikoo Place
979 King's Road
Quarry Bay
Hong Kong
21 August 2026

獨立審閱報告

致晶門半導體有限公司董事會
(於開曼群島註冊成立的有限公司)

引言

本核數師已審閱列載於第3頁至第26頁之晶門半導體有限公司(「貴公司」)及其附屬公司(「貴集團」)2026年6月30日之簡明綜合財務狀況表以及截至該日止6個月期間之有關簡明綜合損益表、全面收入表、權益變動表及現金流量表與說明附註。根據香港聯合交易所有限公司證券上市規則,中期財務資料報告之編製必須符合上市規則之相關規定及香港會計師公會所頒佈之香港會計準則第34號*中期財務報告*(「香港會計準則第34號」)。 貴公司董事須負責根據香港會計準則第34號編製及呈列本中期財務資料。本核數師須負責根據吾等之審閱對本中期財務資料發表結論。吾等之報告乃根據協定之委聘條款,僅向 閣下作為一個實體作出,而非為其他目的。本核數師不會就本報告之內容而對任何其他人士承擔或負上任何責任。

審閱範圍

本核數師乃根據香港會計師公會頒佈之《香港審閱工作準則》第2410號*由實體之獨立核數師對中期財務資料之審閱*進行審閱工作。中期財務資料之審閱包括主要向負責財務及會計事宜之人員作出查詢,並運用分析及其他審閱程序。由於審閱之範圍遠較根據香港審計準則進行之審計為小,因此不能保證本核數師會知悉在審核中可能會發現之所有重大事宜。因此,本核數師不發表審計意見。

結論

根據本核數師之審閱工作,本核數師並無發現任何事宜,使本核數師相信中期財務資料在所有重大方面並無根據香港會計準則第34號之規定編製。

安永會計師事務所
執業會計師

香港鰂魚涌
英皇道979號
太古坊一座27樓
2026年8月21日

CHIEF EXECUTIVE OFFICER'S MESSAGE
行政總裁的話

Dear Shareholders,

In the first half of 2026, the global semiconductor industry continued to undergo structural transformation. Ongoing geopolitical and international trade uncertainties continued to pose challenges to the market. Against a backdrop of weak macroeconomic conditions, the global supply and demand landscape underwent accelerated restructuring, while supply chains experienced profound adjustments and the semiconductor industry became increasingly differentiated amid these changes. Meanwhile, the rapid development of artificial intelligence (AI) applications is reshaping industry resource allocation and investment priorities, driving strong growth in high-end segments such as high-performance computing and high-bandwidth memory. However, intensive mass production in these segments has resulted in increasingly tight wafer foundry capacity, further driving up the Group's production costs. On the demand side, the consumer market has lacked sufficient recovery momentum, while demand for end products has remained weak and price competition has intensified, further squeezing margins across the upstream supply chain. Rising production costs, coupled with the limited pricing flexibility for end products amid challenging economic conditions, have become a common challenge across the consumer electronics industry.

Faced with a complex and challenging external environment, the Group has comprehensively enhanced its operational efficiency by optimising its product portfolio, strengthening supply chain resilience and implementing stringent cost controls. Nevertheless, the Group's gross profit margin and overall profitability came under pressure due to higher upstream wafer foundry prices and rising gold prices.

各位股東：

2026年上半年，全球半導體產業持續經歷結構性轉變。地緣政治及國際貿易環境的不確定性持續為市場帶來挑戰。在宏觀經濟疲弱的背景下，全球供需格局加速重塑，供應鏈經歷深度調整，半導體行業在此變局下更出現明顯分化。與此同時，人工智能(AI)應用的快速發展正重塑產業資源配置及投資方向，帶動高效能運算與高頻寬記憶體等高端領域呈現爆發式增長。然而，該些領域的密集量產導致晶圓廠產能日益緊張，進一步推高本集團的生產成本。需求端方面，傳統消費市場復甦動能不足，終端產品需求維持疲弱，價格競爭日趨激烈，上游供應端利潤進一步壓縮。生產成本上漲，但終端產品價格因經濟環境問題未能大幅提升，是消費性電子產業普遍面對的問題。

面對複雜嚴峻的外部環境，本集團透過優化產品組合、深化供應鏈韌性及嚴格控管成本，全面優化營運效益。惟受制於上游晶圓代工價格走高及黃金價格上升帶來的成本壓力，本集團毛利率與整體盈利表現承壓。

Operational Resilience with Sequential Improvement in the Second Quarter

For the six months ended 30 June 2026 (the "Period"), the Group's sales revenue decreased by approximately 4.8% year on year to US$43.7 million (first half of 2025: US$45.9 million), mainly due to a decline in average selling prices and a slight decrease in shipment volume. In addition, higher wafer costs and the rise in gold prices resulted in the Group's gross profit margin declining to 27.4%, which inevitably had a negative impact on net profit.

Nevertheless, benefiting from the gradual ramp-up of certain new products into mass production from the second quarter, together with the timely implementation of cost optimisation measures, the Group's operating performance improved markedly from the first quarter, demonstrating its adaptability and resilience amid a changing operating environment. Supported by continued enhancements in operational efficiency, the progressive ramp-up and market launch of new products, and effective marketing initiatives, we expect revenue and overall operating performance to improve gradually.

New Products Drive Growth and Product Differentiation

During the Period, the Group's OLED display IC business recorded solid performance. Benefiting from the mass production of drone and action camera projects, the Group recorded growth in both shipment volume and sales revenue from its OLED display IC products, further strengthening the Group's leading position as the world's largest supplier of PMOLED display driver ICs. Shipments of large-size colour e-paper display products continued to grow, driven by strong market recognition of the Gallery 3 colour e-paper notebook solution. The strong performance of these products provided solid support for the Group's shipment volume and stable revenue in the first half of the year, helping mitigate price pressure on end products and underpinning the steady development of the business.

第二季營運逐步改善　營運韌性持續展現

於截至2026年6月30日止六個月(「期內」),受產品平均售價下跌及付運量輕微減少影響,本集團銷售收入較去年同期減少約4.8%至43.7百萬美元(2025年上半年:45.9百萬美元)。此外,晶圓成本增加及黃金價格上升,使本集團的毛利率下降至27.4%,無可避免對淨利潤產生負面影響。

然而,受惠部分新產品自第二季度起逐步量產,加上成本優化措施的及時落地,第二季營運表現相對第一季錄得顯著改善,展現本集團對經營環境變化的適應能力及韌性。受益於營運效益持續釋放,加上新產品陸續量產上市及有效的市場推廣,我們預期收入及整體經營表現將逐步改善。

產品量產付運鞏固收入　差異化產品力持續提升

期內,集團OLED顯示IC業務相對較佳。在無人機及運動相機項目量產帶動下,本集團OLED顯示IC的付運量及銷售收入錄得增長,進一步鞏固本集團作為全球最大的PMOLED顯示驅動IC供應商的領導地位。此外,大型彩色電子紙顯示產品持續出貨,其中Gallery 3彩色電子紙筆記本方案備受市場肯定,付運量隨之提升。該等產品的強勁增長動能,為集團上半年的整體出貨規模與穩健營收提供有力支撐,有效抵禦終端產品的價格壓力,推動業務穩步發展。

In addition, the Group continued to deepen its business development in new display IC products, with particular emphasis on enhancing product differentiation amid intense market competition. The Group actively advanced the development of next-generation colour electronic display label ICs, focusing on E5 (3-bit) and E6 e-paper applications supporting seven or more colours. These IC products have been successfully launched and adopted by customers for module integration designs. In addition to standard IC products, the Group actively collaborated with customers on customised IC projects, including the development of various application solutions using Gate-on-Array (GOA) technology, further enhancing product differentiation and addressing customers' diverse requirements.

此外，本集團持續深化新型顯示IC產品的業務佈局，尤其着重在高度競爭的市場情況下，凸顯產品差異化。本集團積極推進新一代彩色電子顯示標籤IC的研發，聚焦支援七色及以上顯示效果的E5 (3-bit)及E6電子紙應用。相關IC產品已成功推出，並獲客戶導入模組設計。除標準IC產品外，本集團積極與客戶合作開展定制化IC項目，包括採用GOA (Gate-on-Array)技術開發不同應用方案，以提升產品差異化及滿足客戶多元化需求。

Strategic Focus on High-Growth Applications

The Group is focusing on the development of high-value-added IC solutions for high-potential applications, with the aim of enhancing end-product pricing power and building a strong foundation for long-term revenue growth. As the transition towards paperless solutions accelerates, e-paper displays, with their unique advantages such as low power consumption, eye-friendly viewing and IoT compatibility, are rapidly gaining penetration across application areas including educational displays, electronic and advertising signage, smart wearable devices and digital wallets. Among these, demand for commercial display applications remains relatively resilient and sustained, providing a more stable pricing environment. The Group will continue to expand its portfolio of new e-paper display IC products and provide differentiated display solutions featuring multiple colour combinations for different applications, thereby capturing growing demand for upgraded e-paper display IC applications.

聚焦具潛力市場　深化高增值賽道佈局

本集團着眼於高增值、具潛力的IC應用產品發展，提升終端產品的議價能力，築起長遠收入護城河。隨着無紙化趨勢加速推進，電子紙顯示器依託「低功耗、護眼、物聯網相容」等獨特優勢，加速滲透至學習用顯示器、電子及廣告標牌、智慧穿戴裝置、數字錢包等應用領域。其中，商用顯示器的需求更具剛性與持續性，帶來更穩固的價格基礎。集團將完善電子紙顯示IC新產品的佈局，提供多場景多顏色組合的差異化顯示方案，捕捉升級電子紙顯示IC應用的更大需求。

In addition, China's 15th Five-Year Plan focuses on modernisation, driving the accelerated development of emerging and future industries and continued growth in demand for related application-specific ICs. In particular, the penetration of smart cockpits continues to increase, with adoption extending to a broader range of more affordable vehicle models. Meanwhile, the drone market has expanded into a multi-billion-dollar market, supported by a well-established industrial ecosystem and a diversified product portfolio covering both consumer and industrial applications. The Group has taken a forward-looking approach by actively developing related application-specific ICs in these areas, which is expected to further strengthen the foundation for long-term business growth.

Accelerating R&D Innovation and Product Commercialisation

Leveraging years of accumulated technical expertise and R&D investment, the Group's high-value-added new products are progressively entering mass production. The contribution from these products is expected to become increasingly evident, further strengthening the Group's resilience against market headwinds. The Group's large-size e-paper display products are gradually entering the commercialisation phase. In particular, its large-size colour e-paper display driver IC solutions, designed for applications ranging from 20-inch to 75-inch smart media signage and outdoor signage (Spectra™ 6), are expected to enter mass production and shipment in additional sizes in the second half of the year. Products incorporating 16-level greyscale e-paper e-wallet and single-IC, high-resolution black-and-white integrated (All-in-One) IC solutions are also scheduled for market launch in the fourth quarter of 2026.

另外，國家「十五五」規劃聚焦現代化建設，帶動新興產業及未來產業加速發展，相關應用IC需求持續增長。其中，智能座艙的滲透率持續提升，廣泛應用至更多實惠車型，無人機亦擴容為百億美元級市場，形成了覆蓋消費級及工業級的完整產業鏈和多元化產品體系。本集團前瞻佈局，積極發展此等領域的應用IC組合，有望鞏固業務長遠增長的基礎。

新產品規模放量　創新研發提速

依託本集團多年的技術積澱及研發投入，高增值新產品正陸續量產，產品紅利預計持續顯現，增強本集團的抗逆韌性。集團大尺寸電子紙顯示產品逐漸進入收成期，其中目標涵蓋20吋至75吋智慧媒體電子標牌／戶外電子標牌(Spectra™ 6)應用的大尺寸彩色電子紙顯示驅動IC解決方案，預計下半年量產出貨更多尺寸產品，16灰階電子紙錢包及單晶片高分辨率黑白整合式(All-in-One)晶片解決方案的相關產品亦將於2026年第四季推出市場。

To accelerate the market launch of new products, the Group is expediting development efforts and further enhancing its product portfolio to create additional growth drivers for the future. The Group is currently developing driver IC products compatible with E Ink Holdings Inc.'s Prism™ 3 multi-colour e-paper film technology, with samples scheduled for completion in the third quarter of 2026. At the same time, the Group is planning to develop an All-in-One (AIO) integrated e-paper driver IC for large-size e-paper signage applications. Development is expected to commence in the third quarter of 2026, with samples targeted for release in 2027. In the automotive sector, the Group is accelerating the development and testing of its Local Dimming (LoD) bridge IC for automotive head-up displays (HUDs), with the related SoC samples expected to be launched in the fourth quarter of 2026. In addition, an OLED product has been successfully adopted by a gaming terminal customer for integration into its module design. It is expected to enter mass production in the second half of the year and provide strong support for business growth.

為持續推進新產品投入市場，本集團加緊產品開發進程，進一步完善產品佈局，為未來業務發展創造新增長動力。本集團正開發元太科技Prism™ 3多色電子紙薄膜技術的配套驅動IC產品，樣品預計於2026年第三季度完成。同時，本集團同步規劃開發應用於大尺寸電子紙標牌的AIO (All-in-One)整合式電子紙驅動晶片，預計於2026年第三季度啟動開發，並於2027年提供樣品。車載領域方面，本集團將加快車用HUD抬頭顯示器（LoD局部調光橋接IC）的開發及測試工作，力爭於2026年第四季度推出相關SoC樣品。此外，一款OLED產品成功獲遊戲終端產品客戶採用於模組設計，預期將於下半年投入量產，為業務增長提供有力支持。

Outlook and Strategy for the Second Half of the Year

Looking ahead to the second half of the year, geopolitical uncertainties are expected to remain elevated, while continued volatility in the supply chain may add further uncertainty to international trade. Against the backdrop of slowing global economic growth, customer demand is likely to remain subdued, which may continue to weigh on the recovery of end-product prices. At the same time, demand for AI-related products is expected to remain strong, while wafer supply is expected to remain tight and pricing at elevated levels. To maximise operational efficiency, the Group will continue to pursue a prudent operating strategy, advance the mass production of new products as planned, actively mitigate upstream cost pressures, and deepen its presence in high-value-added segments to strengthen the foundation for long-term development. Given the continuing bottlenecks in wafer supply, the Group has entered into medium- to long-term supply agreements with major wafer foundries to secure stable supply. The benefits of these arrangements are expected to materialise gradually, supporting the Group's profitability.

下半年展望與策略

展望下半年，全球地緣政治風險仍處高位，供應鏈波動或將持續反覆，為國際貿易增添不確定性。在全球經濟增長放緩的背景下，消費復甦動能或受制約，對終端產品價格回暖構成一定壓力。與此同時，AI應用產品需求持續強勁，晶圓價格預期持續緊張。為實現營運效率最大化，本集團將繼續秉持穩健經營策略，推進新產品如期量產以貢獻營收，積極對沖上游成本壓力，同時深化高增值賽道佈局，鞏固長遠發展基礎。鑒於當前晶圓供應仍存瓶頸，集團已與主要晶圓廠簽訂中長期供應協議，以確保供應穩定。相關安排之效益預期將於未來逐步體現，有助鞏固集團的盈利能力。

In terms of products, the Group will continue to leverage its leading position in e-paper and OLED display driver ICs and capture growth opportunities in high-value-added applications such as electronic shelf labels, e-paper, smart wearable devices and smart cockpits. The Group will also actively advance multiple R&D projects and accelerate the commercialisation and mass production of high-quality products, thereby enhancing its pricing power and overall resilience while driving sustainable business growth.

產品方面，集團將持續把握於電子紙及OLED顯示驅動IC領域的領先優勢，捕捉IC產品在電子標籤、電子紙、智能穿戴設備及智能座艙等高附加值應用領域的增長機遇，集團亦將積極推進多項研發項目，加快高質量產品的量產落地，提升產品溢價能力及整體抗風險能力，從而推動業務的可持續增長。

On behalf of the Group, I would like to express my sincere gratitude to all members of the management team and our employees. In the face of a complex and challenging operating environment, their professionalism, dedication and unwavering sense of responsibility have provided strong support for the Group's stable operations. I would also like to express my heartfelt thanks to all shareholders, investors and business partners for their longstanding trust and support. Looking ahead, we will continue to move forward together, deepen our commitment to technological innovation, seize opportunities arising from industry development and drive the Group towards high-quality and sustainable development, thereby creating greater value for our shareholders.

本人謹代表集團，向全體管理層及員工致以誠摯感謝。面對複雜嚴峻的經營環境，大家始終秉持專業精神與不變的責任感，為公司穩健運營帶來保障。同時，衷心感謝各位股東、投資者及合作夥伴長期以來的信任與支持。展望未來，我們將繼續攜手前行，深化技術創新佈局，把握行業發展機遇，推動本集團實現高質量、可持續發展，以更大的價值回饋股東。

Wang Wah Chi, Raymond
Chief Executive Officer

Hong Kong, 21 August 2026

王華志
行政總裁

香港，2026年8月21日

BUSINESS REVIEW & OUTLOOK

Business Review

In the first half of 2026, sustained investment in AI-related infrastructure continued to drive robust demand for GPU, memory, storage, and power management related ICs, resulting in high utilisation in foundry capacity. As these products share certain foundry resources with display driver ICs, persistently high capacity utilisation at foundries has driven up wafer prices, resulting in higher production costs for the Group. In response to evolving market conditions, the Group has continued to optimise its product portfolio, strengthen supply chain management and implement cost-control measures to enhance operational efficiency. Nevertheless, rising wafer and gold prices have continued to adversely affect the Group's gross profit margin and overall profitability.

For the six months ended 30 June 2026 (the "Period"), the Group's shipment volume declined by approximately 3.8% year on year to approximately 153.7 million units, compared with 159.7 million units in the same period last year. The decrease was mainly attributable to the delayed launch of the latest generation products, although part of the impact was offset by the commencement of mass production of other products.

Amid continued price reductions in end products and intensifying market competition, the average selling price of the Group's products declined. Together with a slight decrease in shipment volume, this resulted in the Group's revenue decreasing by approximately 4.8% year on year, from US$45.9 million to US$43.7 million. In addition, rising wafer costs and the increase in gold prices, which substantially drove up production costs, resulted in the Group's gross profit margin decreasing to 27.4% during the Period.

The Group's performance in the second quarter improved significantly compared with the first quarter, benefiting from the gradual mass production of certain products from the second quarter of 2026 and the progressive effectiveness of its cost-control measures. However, as production costs remained higher than those in the same period last year, the Group still recorded a loss during the Period.

業務回顧及展望

業務回顧

2026年上半年，受AI相關設備投資拉動，導致GPU、記憶體、儲存以及電源相關IC需求持續增長，帶動晶圓代工產能需求維持高位。由於相關產品與顯示驅動IC共享部分晶圓製造資源，晶圓廠產能利用率長期高企致晶圓價格上升，增加本集團的生產成本。面對市場環境變化，本集團持續優化產品組合、加強供應鏈管理及推行成本控制措施，以提升營運效率。然而，晶圓及黃金價格上漲仍對本集團毛利率及盈利能力帶來一定影響。

截至2026年6月30日止六個月(「期內」)，本集團付運量較去年同期(159.7百萬件)減少約3.8%至約153.7百萬件，主要由於新一代產品推出時間較原定計劃延後，惟部分影響已被其他產品投入量產所抵銷。

受終端產品持續降價及市場競爭加劇影響，產品平均售價有所下跌，加上付運量輕微減少，本集團銷售收入較去年同期(45.9百萬美元)減少約4.8%至43.7百萬美元。此外，受晶圓成本增加及黃金價格上升影響，帶動生產成本增加，使本集團於期內的毛利率下降至27.4%。

受惠於部分產品於2026年第二季起陸續投入量產，加上成本控制措施逐步見效，本集團第二季度相對第一季表現已有明顯改善。然而，由於生產成本較去年同期上升，本集團於期內仍錄得虧損。

Looking ahead to the second half of the year, with new products being progressively launched and the relevant projects gradually entering into mass production, together with steady progress in marketing initiatives, the Group expects its revenue and operating performance to improve gradually. The Group will continue to optimise its product portfolio, strengthen supply chain management, enhance cost control and capacity planning, with a view to improving overall operational efficiency and market competitiveness.

展望下半年，隨著新產品陸續推出市場及相關項目逐步量產，加上市場推廣工作穩步推進，本集團預期收入及經營表現有望逐步改善。本集團將繼續優化產品組合、強化供應鏈管理、加強成本控制及產能部署，以提升整體營運效益及市場競爭力。

New Display ICs

New display IC products primarily refer to the Group's bistable display products. Bistable display is a non-traditional display technology in which the display device is illuminated by reflecting ambient light.

Electronic shelf labels ("ESLs") enable flexible price updates, enhance operational efficiency and facilitate inventory management. They can not only reduce long-term costs, but also help lower retailers' carbon footprints, in line with the global trend towards paperless and sustainable operations. These advantages have driven the widespread adoption of ESLs in Europe and North America, while their use has also been gaining traction in Asian countries in recent years. The Group has been an early mover in this market, having focused on the development of ESL IC products for many years. ESLs using our ICs are now in a number of leading supermarket chains worldwide.

The three-colour (E4) and four-colour (E5) electronic display labels available on the market have completed their upgrade cycles, and the Group has likewise completed the specification upgrades for all models of its four-colour display labels. Meanwhile, the market is moving towards multi-colour display specifications to meet retailers' growing demand for enhanced customer experience and product differentiation. In view of this market upgrade trend, the Group is actively developing a new generation of colour electronic display label IC products, focusing on E5 (3-bit) and E6 e-paper applications supporting seven-colour and above display capabilities. During the Period, the Group successfully launched a series of such IC products, including SSD2692, SSD2693, SSD2695, SSD2690 and SSD2696 (3-bit). These products have been adopted by customers for module design, laying a solid foundation for future mass production and market penetration.

新型顯示IC

新型顯示IC產品主要指本集團之雙穩態顯示產品。雙穩態顯示是一種非傳統的顯示技術，顯示設備通過反射環境光來照明。

電子貨架標籤既能靈活更新價格、提高效率，亦易於庫存管理，不僅可降低長期成本，更可減少商戶的碳足跡，迎合無紙化可持續發展的全球趨勢。眾多優點令電子貨架標籤不僅在歐洲及北美普及，近年在亞洲國家亦成為新興趨勢。本集團早着先機，多年來專注發展電子貨架標籤IC產品，相關方案已獲全球多家領先超級市場採用。

市場上的三色(E4)、四色(E5)電子顯示標籤已完成更新換代，本集團亦已完成四色顯示標籤所有型號的制式更新。與此同時，市場正朝著更多色彩顯示規格發展，以滿足零售商對提升顧客體驗及產品差異化的需求。為配合市場升級趨勢，本集團積極開發新一代彩色電子顯示標籤IC產品，專注於支援七色及以上顯示效果的E5 (3-bit)及E6電子紙應用。期內，本集團已成功推出該系列IC產品，包括SSD2692、SSD2693、SSD2695、SSD2690和SSD2696 (3-bit)，並已獲客戶導入模組設計，為未來量產及市場滲透奠定基礎。

During the Period, shipment volume of the Group's new display IC products decreased slightly compared with the corresponding period last year. Amid intensified market competition and a decline in average selling prices, revenue from the related business also decreased slightly year on year. In addition, continued tightness in wafer supply and rising production costs resulted in a year-on-year decline in the gross profit margin of these products. Starting from the second half of the year, the Group secured medium- to long-term supply agreements with major wafer suppliers, and wafer supply is expected to become relatively stable.

期內，本集團新型顯示IC產品的付運量較去年同期輕微下跌。受市場競爭加劇及產品平均售價下降影響，相關業務收入亦較去年同期錄得輕微跌幅。此外，由於晶圓供應持續緊張及生產成本上升，相關產品毛利率亦較去年同期有所回落。下半年起，本集團已與主要晶圓供應商訂立中長期供應協議，預期晶圓供應將會相對穩定。

In addition to standard IC products, the Group has been actively collaborating with customers on customised IC projects, such as developing application solutions using Gate-on-Array ("GOA") technology to enhance product differentiation and meet customers' diverse needs. The Group will continue to enrich its customised IC product portfolio to cope with market demand, thereby expanding business opportunities and strengthening its market competitiveness.

除標準IC產品外，本集團亦積極與客戶合作開展定制化IC項目，包括採用GOA (Gate-on-Array)技術開發不同應用方案，以提升產品差異化及滿足客戶多元化需求。本集團將因應市場需求持續豐富定制化IC產品組合，進一步拓展業務機會及增強市場競爭力。

Apart from that, the Group continues to explore applications of e-paper technology beyond ESLs. Building on the development of E Ink Holdings Inc.'s Prism™ 3 multi-colour e-paper film technology, this segmented e-paper technology enables dynamic colour changes across a wide range of applications, including home appliances, vehicle exteriors, interior décor and wearable products, allowing for greater product personalisation. Prism™ 3 can be freely cut and applied to three-dimensional surfaces, significantly enhancing its application flexibility in different areas. The Group is currently developing corresponding driver IC products, with samples expected to be completed in the third quarter of 2026. This will further broaden the application opportunities for e-paper technology in the consumer, smart home and industrial markets.

另一方面，本集團持續推動電子紙技術於電子貨架標籤以外的應用領域。配合元太科技Prism™ 3多色電子紙薄膜技術的發展，該段碼技術可為家電、車身、室內裝飾和穿戴式產品等不同領域和應用實現顏色動態變化，令產品更個性化。Prism™ 3不但可以自由切割，而且可以貼附於立體表面，大大提高了應用的彈性和可能性。本集團正開發配套驅動IC產品，樣品預計於2026年第三季度完成，進一步拓展電子紙技術於消費、智能家居及工業市場的應用機遇。

Looking ahead to the second half of the year, with the continued advancement of colour e-paper technology and growing demand from end customers for enhanced display performance and product differentiation, the e-paper market is expected to sustain steady growth. The Group will continue to advance new product development and expand applications, while deepening collaboration with customers and industry partners to capture the opportunities in these markets.

展望下半年，受惠於彩色電子紙技術持續升級，以及終端客戶對顯示效果及產品差異化需求日益增加，電子紙市場預期將保持穩步發展。本集團將持續推進新產品開發及應用拓展，並深化與客戶及產業鏈夥伴的合作，以把握相關市場機遇。

Meanwhile, amid persistently strong wafer demand and tight capacity supply, production costs are expected to remain relatively high in the second half of the year, while product prices will be adjusted in response to overall supply and demand conditions. The Group will mitigate the impact of rising costs on business performance by optimising supply chain management, strengthening cost control and enhancing operational efficiency, thereby reinforcing the foundation for long-term growth.

與此同時，受晶圓需求持續高企及產能供應緊張影響，預期下半年生產成本仍將維持於較高水平，而產品價格亦將因應整體供需環境變化而有所調整。本集團將透過優化供應鏈管理、強化成本控制及提升營運效率，減輕成本上升對業務表現的影響，並鞏固長遠發展基礎。

OLED Display ICs

Solomon Systech offers a comprehensive portfolio of OLED display driver ICs for a broad range of applications, including passive matrix OLED ("PMOLED"), mini/micro-LED and icon IC products. The Group is the world's largest supplier of PMOLED display driver ICs and holds a leading global market share based on the shipment volume during the Period. The Group offers a comprehensive range of PMOLED driver ICs, from icon-based to dot-matrix formats, and from monochrome and greyscale displays to fully integrated full-colour solutions, making them ideal display solutions for portable electronic devices. During the Period, driven by the mass production of drone and action camera projects, the Group recorded growth in both the shipment volume and sales revenue of its OLED display IC products.

OLED顯示IC

晶門半導體提供多種OLED顯示驅動IC，應用廣泛，包括被動式OLED(「PMOLED」)、mini/micro-LED和圖標IC (icon IC)產品等。集團是全球最大的PMOLED顯示驅動IC廠商，按期內付運量計算，市場份額佔主導地位。本集團提供從圖標到點陣，從單色和灰階顯示到全彩色高度集成的全系列PMOLED驅動IC，是便攜式設備的理想顯示解決方案。期內，受無人機及運動相機項目進入量產階段帶動，本集團OLED顯示IC的付運量及銷售收入均錄得增長。

The Group offers a range of cost-competitive icon ICs. Since their launch in 2023, customers have continued to launch and market end products incorporating these icon ICs. Designed for displays ranging from 1 to 4 inches, these icon ICs are suitable not only for portable devices but also support the Group's expansion into the large-panel segment of the smart home appliance market. Smart appliances have become an increasingly prominent market trend, and the Group will continue to monitor the growing demand for smart home solutions and Internet of Things ("IoT") applications. During the Period, the Group also continued to promote its newly developed IC products supporting transparent PMOLED displays. Transparent PMOLED is an emerging technology that can be applied to end products requiring see-through displays, such as diving masks and golf ball tracking glasses. In addition, one of the Group's OLED products was successfully adopted by a gaming terminal customer for module design and is expected to enter mass production in the second half of the year, providing further support for business growth.

本集團提供一系列具價格競爭力的圖標IC，自2023年產品推出至今，該產品之客戶持續就使用了此系列圖標IC的終端產品進行推廣。本集團的圖標IC針對1至4英寸的顯示器，除應用於便攜式產品，亦可為本集團拓闊智能家電的大面板市場。智能家電產品在市場上已是大勢所趨，本集團將繼續關注持續增長的智能家居解決方案和物聯網(IoT)的市場需求。本集團並於期內繼續推廣其新研發可支持PMOLED透明顯示屏的IC產品，透明PMOLED顯示屏是一種新型技術，可應用於潛水鏡、高爾夫球探球眼鏡等需要透明顯示的終端應用。此外，一款OLED產品亦成功獲遊戲終端產品客戶採用於模組設計，預期將於下半年投入量產，為業務增長提供支持。

The Group is also a pioneer in mini/micro-LED applications. Its mini-LED display driver IC (DDI) solution for 50- to 100-inch indoor display signage has been in mass production since 2018. The solutions are currently deployed by film studios in the United States to create dynamic virtual scenes on filming sets. In 2023, the Group launched the world's first small-sized passive micro-LED display driver IC, the SSD2363. The product supports next-generation, high-brightness 16.7-million-colour displays of 3 inches or smaller, making it suitable for applications including wearable devices, home appliances and industrial equipment. Currently, the IC is primarily supplied to customers for validation and functional testing of micro-LED features in their end products. The Group is also actively engaging with customers across different segments to drive adoption of the IC in various high value-added projects, including the portable electronics market.

本集團亦是mini/micro-LED應用的先行者，用於50至100英寸室內顯示標牌的mini-LED DDI解決方案自2018年至今一直在量產，現時由美國電影製片廠採用，用於打造拍攝現場的動態虛擬場景。本集團於2023年推出全球首枚小尺寸被動式microLED顯示驅動IC－SSD2363，該產品可應用於3英寸或以下的新一代高亮度16.7M彩色顯示屏，適用於穿戴裝置、家用電器及工業應用。此IC產品現時以供客戶驗證測試其終端產品micro-LED功能的用途為主，本集團亦正積極接觸不同類型的客戶，以推動相關產品應用到各高增值項目，例如便攜式電子產品市場等。

Meanwhile, the reduction in the market supply of 8-inch wafers, due to production capacity adjustments by certain foundries, has resulted in increasingly tight supply of 8-inch wafers, presenting certain challenges in supply chain management for OLED display IC products. To ensure a stable product supply and meet customer demand, the Group has implemented appropriate production capacity allocation and deployment measures, including entering medium- to long-term agreements with wafer foundries to secure supply. These arrangements are progressing smoothly and are expected to provide ongoing support for product supply in the coming years, while enhancing supply assurance and operational resilience. Leveraging its stable customer base and continued introduction of new products, the Group will continue to capitalise on growth opportunities in the drone, smart device and other high value-added application markets.

另一方面，因部分晶圓代工廠調整產能配置，導致市場上8吋晶圓供應減少，令8吋晶圓供應趨於緊張，對OLED顯示IC產品的供應鏈管理帶來一定挑戰。為確保產品供應穩定及滿足客戶需求，本集團已採取適當的產能調配及佈局措施，包括與晶圓廠訂立中長期協議以穩定供應，相關安排進展順利，預期將於未來陸續為產品供應提供支持，並有助提升供應保障能力及營運韌性。憑藉穩定的客戶基礎及持續推出新產品，本集團將繼續把握無人機、智能設備及其他高增值應用市場的發展機遇。

Mobile Display and Mobile Touch ICs

Solomon Systech offers a broad range of mobile display and mobile touch IC solutions and continues to expand its product portfolio. Its offerings include In-Cell Touch display driver ICs, TFT display driver ICs, STN display driver ICs, MIPI bridge ICs and display controller ICs, supporting a wide range of industrial and consumer products, including smartphones, tablet computers, wearable devices, gaming devices and IoT equipment. The Group is a pioneer in MIPI display solutions and offers a range of proprietary features that support high-resolution, high-speed and low-power display performance for smart devices.

移動顯示及移動觸控IC

晶門半導體提供多種移動顯示及移動觸控IC解決方案，不斷擴闊產品組合，包括內嵌式觸控顯示驅動IC、TFT顯示驅動IC、STN顯示驅動IC、MIPI橋接IC和顯示控制IC，支持廣泛的工業和消費產品，如智能手機、平板電腦、可穿戴設備、遊戲裝置和物聯網設備等。本集團是MIPI顯示解決方案的先驅，提供一系列專有功能，支持智能設備的高分辨率、高速和低功耗顯示。

During the Period, both shipment volume and sales revenue from the Group's mobile display and mobile touch IC products decreased compared with the same period last year. This was mainly attributable to rising prices of key components, such as memory and solid-state drives, which increased the overall costs and retail prices of end products, thereby affecting market demand. In addition, certain supply chain constraints affected product shipments, resulting in a decline in the sales performance of these products compared with the same period last year.

期內，本集團移動顯示及觸控IC產品的付運量及銷售收入均較去年同期下跌，主要由於記憶體及固態硬碟等關鍵元件價格上升，推高終端產品整體成本及零售價格，影響市場需求；加上部分供應鏈限制對出貨造成影響，令相關產品銷售表現較去年同期有所回落。

The Group has extensive experience in TDDI technology, with its game controller ICs designed to deliver greater control accuracy, faster response times and longer battery life. Leveraging these technological advantages, the Group remains attentive to emerging opportunities in the consumer market and high-value-added application areas such as automotive displays, as well as evolving demand trends for high-brightness and outdoor display applications, with a view to further enhancing the competitiveness of its products. Meanwhile, development of the Local Dimming ("LoD") bridge IC for automotive head-up displays ("HUDs") is progressing steadily, with related samples expected to be completed during the year.

本集團在TDDI技術領域擁有豐富經驗，設計的遊戲控制器IC能讓操控更準確、反應更快捷而電池運行時間更長。憑藉相關技術優勢，本集團積極關注消費市場及車載顯示等高增值應用領域的發展機遇，以及高亮度及戶外顯示場景的市場需求變化，以進一步提升產品競爭力。然而，應用於車用HUD抬頭顯示器的LoD局部調光橋接IC開發工作持續推進，相關樣品預計將於年內完成。

Looking ahead to the second half of the year, the Group will continue to expand applications for its mobile display and mobile touch ICs across a broader range of fields, including actively pursuing design projects for next-generation game controllers, with a view to extending product lifecycles and capturing a greater share of the market. In addition, the Group will accelerate the development and testing of its LoD bridge IC for automotive HUDs, with the aim of completing and launching the relevant SoC samples in the fourth quarter of 2026. The Group will actively promote these products to customers and pursue project opportunities. The Group will also continue to engage with customers across a range of end-product segments to gain a deeper understanding of their requirements and develop products tailored to specific applications.

展望下半年，本集團持續拓展移動顯示及移動觸控IC應用到更多不同領域，包括積極爭取下一代遊戲控制器設計項目，以延長產品生命週期及爭取更多市場份額。此外，本集團將加快車用HUD抬頭顯示器（LoD局部調光橋接IC）的開發及測試工作，並力爭於2026年第四季度完成相關SoC樣品推出，積極向客戶推廣並爭取項目機會。本集團將繼續接觸生產不同終端產品的客戶，以收集和了解其需求來開發出切合個別應用的產品。

Large Display ICs

The Group remains committed to collaborating with leading display panel manufacturers in China and overseas to develop a comprehensive range of large display driver IC solutions. These solutions support a wide range of applications, including commercial displays, high-end gaming monitors, smart televisions of various sizes, as well as medium- and large-format colour e-paper signage, e-paper bulletin boards, e-book readers and e-wallets.

大型顯示IC

本集團致力於與國內外顯示屏大廠開發多種大尺寸顯示驅動IC解決方案，支持商用顯示器、高階電競顯示器、各尺寸智能電視，以及中、大型彩色電子紙標牌、電子紙佈告欄、電子書閱讀器和電子錢包等應用。

During the Period, the Group's large display IC business maintained stable performance, with continued shipments of new colour e-paper display products. In particular, the Gallery 3 colour e-paper notebook solution, which is already in mass production, continued to gain market adoption, providing a stable revenue contribution to the relevant business and driving shipment volume growth compared with the same period last year.

期內，本集團大型顯示IC業務表現穩定，新型彩色電子紙顯示產品持續出貨，其中已量產的Gallery 3彩色電子紙筆記本方案持續獲市場採用，為相關業務帶來穩定收入貢獻，並帶動付運量較去年同期有所增長。

In the e-paper display market, the Group is actively adopting large-size colour e-paper display driver IC solutions featuring the miniLVDS interface, targeting applications ranging from 20-inch to 75-inch smart media signage and outdoor e-paper signage (Spectra™ 6). During the Period, end-product validation of the relevant solutions across various sizes commenced. Certain products have successfully entered mass production, while mass production and shipments of the remaining sizes are expected to commence in the second half of the year. Meanwhile, the Group is progressing the development of a 16-level greyscale e-paper e-wallet solution and a single-IC, high-resolution black-and-white integrated (All-in-One) IC solution. The relevant products are expected to be launched in the fourth quarter of 2026, enabling the Group to capitalise on growth opportunities in the portable e-paper device market.

在電子紙顯示市場方面，本集團積極採用miniLVDS介面的大尺寸彩色電子紙顯示驅動IC解決方案，目標涵蓋20吋至75吋智慧媒體電子標牌／戶外電子標牌(Spectra™ 6)應用。期內，相關方案已展開不同尺寸產品的終端驗證工作，部分尺寸產品已成功投入量產，其餘尺寸產品預計將於下半年開始量產出貨。同時，本集團正推進16灰階電子紙錢包及單晶片高分辨率黑白整合式(All-in-One)晶片解決方案，相關產品預計於2026年第四季度推出市場，以把握便攜式電子紙設備市場的增長機遇。

Looking ahead to the second half of the year, the Group will continue to secure additional wafer capacity to support mass production projects for e-paper notebooks and e-paper signage and meet growing customer demand. At the same time, the Group will accelerate the promotion of its E6 e-paper display driver solutions. In addition to existing mass production projects, the Group will actively expand its customer base to include more display panel manufacturers and end-product customers, thereby further broadening its market coverage. Meanwhile, development of the single-IC, high-resolution black-and-white integrated IC solution will proceed as planned, with mass production and shipments to customers scheduled for the fourth quarter. Furthermore, the Group is planning to develop an AIO (All-in-One) integrated e-paper driver IC for large-size e-paper signage. It is expected to commence in the third quarter of 2026, with samples expected to be available in 2027. This will further enhance the Group's product portfolio and create new growth momentum for its future business development.

展望下半年，本集團將繼續爭取更多晶圓產能，以支持電子紙筆記本及電子紙標牌等量產項目，滿足客戶需求增長。同時，本集團將加快推廣E6電子紙顯示驅動方案，除現有量產項目外，亦積極拓展至更多顯示面板廠商及終端應用客戶，進一步擴大市場覆蓋。另一方面，單晶片高分辨率黑白整合式晶片方案將按計劃推進，配合客戶於第四季度量產出貨。此外，本集團正規劃開發應用於大尺寸電子紙標牌的AIO (All-in-One)整合式電子紙驅動晶片，預計於2026年第三季度啟動開發，並於2027年提供樣品，進一步完善產品佈局，為未來業務發展創造新增長動力。

Outlook

Looking ahead to the second half of the year, the global economic and geopolitical environment remains subject to considerable uncertainty. Frequent changes in United States tariff policies and trade measures may affect global supply chains and market demand. Meanwhile, sustained strong demand for GPU, memory, storage, and power management related ICs is keeping foundry capacity tight and expected to continue to exert cost pressure on the display driver IC industry. Against this complex operating environment, the Group will continue to optimise its product portfolio and supply chain strategy, while strengthening cost control and enhancing operational efficiency to improve its overall competitiveness.

In terms of product development, the Group will continue to focus on e-paper, OLED display and other high value-added application markets. In the e-paper business, products including seven-colour electronic display labels, Gallery 3 colour e-paper notebooks, single-IC high-resolution black-and-white integrated (All-in-One) IC and E6 e-paper signage driver solutions will progressively enter the customer validation, product introduction and mass production stages, and are expected to provide new sources of revenue for the Group. At the same time, the Group will continue to advance the development of Prism™ 3, GOA technology and other customised IC projects, further expanding market opportunities for e-paper technology in consumer electronics, smart home and industrial applications. In addition, the mini-LED backlighting solution incorporating a LoD bridge IC for automotive HUDs will be launched in the second half of the year.

Leveraging its ample resources, technological expertise and diversified product portfolio, the Group will continue to advance the development and commercialisation of new products, while deepening collaboration with customers and partners to seize market opportunities and drive steady business growth.

展望

展望下半年，全球經濟及地緣政治環境仍存在不少不確定因素。美國關稅政策及貿易措施變化頻繁，或對全球供應鏈及市場需求帶來影響。同時，GPU、記憶體、儲存以及電源相關IC需求持續強勁，帶動晶圓代工產能維持緊張，預期將繼續為顯示驅動IC產業帶來成本壓力。面對複雜的經營環境，本集團將持續優化產品組合及供應鏈佈局，並加強成本控制及營運效率，以提升整體競爭力。

產品發展方面，本集團將繼續聚焦電子紙、OLED顯示及其他高增值應用市場。在電子紙業務方面，七色電子顯示標籤、Gallery 3彩色電子紙筆記本、單晶片高分辨率黑白整合式(All-in-One)晶片，以及E6電子紙標牌驅動方案等產品將陸續進入客戶驗證、導入及量產階段，有望為集團帶來新的收入來源。同時，本集團亦將持續推進Prism™ 3、GOA技術及其他定制化IC項目開發，進一步拓展電子紙技術於消費電子、智能家居及工業應用等領域的市場機遇。除此以外，應用於車用HUD抬頭顯示器（LoD局部調光橋接IC）的mini-LED背光方案亦將於下半年推出市場。

本集團憑藉充足的資源、穩健的技術實力及多元化的產品組合，將繼續推進新產品開發及商業化進程，並深化與客戶及合作夥伴的協作，以把握市場機遇，推動業務穩健發展。

FINANCIAL REVIEW

Revenue and Results Overview

The Group recorded a decrease of about 4.8% in revenue to US$43.7 million during the Period (1H 2025: US$45.9 million). The gross profit of US$12.0 million and gross margin of 27.4% were recorded during the Period (1H 2025: US$18.2 million and 39.6%, respectively). The decrease in revenue, gross profit and gross profit margin was mainly attributable to the increase in the cost of production, which arose from semiconductor supply chain bottlenecks in the global chip ecosystem, that led to increase in production cost, and also constrained output despite growing demand.

Selling and distribution expenses of US$1.7 million represented an increase of 4.4%, while general and administrative expenses of US$5.3 million, represented an increase by 1.8%, respectively, as compared to the corresponding period of last year. The Group will continue the on-going effective stringent cost control measures to enhance operational efficiency.

The Group has allocated resources to the products that more adopt with the global market trends and market needs and remains selective in its product R&D spending. The R&D costs during the Period amounted to US$10.2 million (1H 2025: US$9.9 million), representing an increase of 3.0%, the R&D costs to sales ratio for the Period was about 23.4% of the total revenue for the six months ended 30 June 2026 (1H 2025: 21.6%), an increase of 1.8 percentage points when compared with the same period of last year. The Group is committed to its long-term development and has set a bold target in R&D for innovation to solidify its leading position in IC display industry.

財務回顧

收入及業績回顧

本集團期內收入下跌約4.8%至43.7百萬美元(2025年上半年:45.9百萬美元)。期內的毛利和毛利率分別為12.0百萬美元和27.4%(2025年上半年:分別為18.2百萬美元和39.6%)。銷售額、毛利及毛利率減少主要由於生產成本因全球晶片生態系統中的半導體產業鏈出現瓶頸而增加,產出即使在需求增長的情況下受限。

銷售及分銷開支為1.7百萬美元較去年增加4.4%,行政及一般開支為5.3百萬美元,較去年同期增加1.8%。本集團將繼續實施現行有效且嚴格的成本控制措施以提高營運效率。

本集團已將資源投放在更貼近全球市場趨勢的產品上,在產品工程研發支出方面保持審慎。其於期內的工程研發費用為10.2百萬美元(2025年上半年:9.9百萬美元),上升3.0%,約佔截至2026年6月30日止6個月總銷售額的23.4%(2025年上半年:21.6%),與去年同期比較上升1.8個百分點。為著提高我們的長期競爭力,本集團致力於科研投入,並已創新研發設立宏大目標,務求鞏固於IC顯示器行業的領導地位。

The Group reported a net loss attributable to owners of the parent of US$4.0 million during the Period (1H 2025: net profit US$4.0 million). The Board does not recommend a payment of an interim dividend for the six months ended 30 June 2026.

本集團於期內錄得母公司擁有人應佔淨損失為4.0百萬美元（2025年上半年淨溢利：4.0百萬美元）。董事會不建議宣派截至2026年6月30日止6個月的中期股息。

Despite the decrease in unaudited consolidated profit attributable to shareholders in the first half of 2026 when compared with the first half of 2025, the Group is still able to maintain a stable IC shipment volumes in the first half of 2026, which shows the Group's capability to maintain a stable market share despite unfavourable market conditions. At the same time, we have sufficient resources to support our continued commitment to research and development projects, which is critical to sustain the long-term competitiveness of the Group.

儘管2026年上半年之股東應佔未經審核綜合溢利較2025年上半年有所下降，惟董事會謹此強調，本集團於2026年上半年仍能維持穩定的IC付運量，顯示本集團即使於不利的市場狀況下，仍有能力維持穩定的市場份額。與此同時，我們會繼續投入資源支持本集團不同研發項目以維持本集團的長遠競爭力。

Liquidity and Financial Resources

流動資金及財務資源

		Unaudited 未經審核 30 June 6月30日 2026 US$'000 千美元	Audited 經審核 31 December 12月31日 2025 US$'000 千美元
Current assets	流動資產	**154,278**	153,523
Current liabilities	流動負債	**24,401**	21,912
Net current assets	流動資產淨值	**129,877**	131,611
Current ratio	流動比率	**6.3**	7.0

The Group's current ratio was 6.3 as at 30 June 2026 (31 December 2025: 7.0), reflecting a strong liquidity in its financial position. The working capital position, represented by net current assets was US$129.9 million (31 December 2025: US$131.6 million), which had no significant adverse change from the last financial year-end.

於2026年6月30日，本集團的流動比率為6.3（2025年12月31日：7.0），反映集團財務狀況具有強健的流動資金水平。流動資產淨值所代表的營運資金狀況為129.9百萬美元（2025年12月31日：131.6百萬美元），與去年財務年結相比並無顯著不利變化。

The Group has invested in financial assets (mainly bank deposits) as part of its treasury management for interest income. During the Period, the Group recorded an interest income of US$1,607,000 (1H 2025: US$2,171,000).

本集團投資於財務資產（主要為銀行存款）作資金管理以獲取利息。於回顧期內，本集團錄得利息收入1,607,000美元（2025年上半年：2,171,000美元）。

Treasury Management

The Group has an internal treasury review team (the "Team") to execute treasury management policy, review the overall investment portfolio and monitor the performance on a regular basis to increase the yield of cash reserves. The Team conducts regular review meetings or teleconferences with individual external portfolio managers and holds internal review meetings to evaluate and monitor the investment performance.

Total cash and cash equivalents and pledged bank deposits of the Group were US$110.5 million as at 30 June 2026 (31 December 2025: US$106.9 million), an increment of US$3.6 million, of which US$2.5 million denominated in US dollars (31 December 2025: US$2.5 million) were pledged to banks to secure general banking facilities for general operating purposes. Cash and cash equivalents and bank deposits of the Group were mainly denominated in US dollars, New Taiwan dollars, Australian dollars, Hong Kong dollars and Renminbi.

The Group will continue to allocate funds for product development, securing production capacity, broadening its customer base and capturing market and sales opportunities, entering into strategic corporate ventures and meeting general corporate operational purposes. The Group will also continue to execute its treasury management policy to enhance the yield of cash reserves during the Period of low interest return. As at 30 June 2026, the Group had no major borrowing. The Group's cash balance was mainly invested in various deposits in banks.

Most of the Group's trade receivables and payables are denominated in US dollars. The Group closely monitors the movement of foreign exchange rates and constantly seeks to obtain favourable exchange rates for conversion of US dollars into other currencies for paying local operating expenses. During the Period, the Group did not use any derivative instruments to hedge against foreign currency exposure in its operations as the Board considered this exposure to be insignificant.

庫務管理

本集團設有內部庫務審閱小組(「小組」),負責執行庫務管理政策、審閱整體投資組合及定期監察投資表現以提升現金儲備的回報率。該小組定期與外聘之投資組合管理經理進行會面或電話會議及舉行內部審閱會議以檢討及監察投資表現。

於2026年6月30日,本集團的現金及現金等價物及已抵押銀行存款總計為110.5百萬美元(2025年12月31日:106.9百萬美元),增加3.6百萬美元。當中2.5百萬美元以美元計值(2025年12月31日:2.5百萬美元)屬抵押存款予銀行作融資營運用途。現金及現金等價物和銀行存款主要以美元、新台幣、澳元、港元及人民幣結算。

本集團將繼續分配資源於產品開發、保障產能、擴大顧客群及把握市場及銷售商機、進行若干策略性企業投資及用作一般公司營運用途。本集團亦將繼續執行庫務管理政策,於低利率期間增加現金儲備之回報率。於2026年6月30日,本集團並無任何主要借貸。本集團之現金餘額主要投資於銀行各類存款。

本集團的主要應收及應付款均以美元結算。本集團會密切監察外幣兌換率的變動,以確保能夠以有利的兌換率將美元兌換成其他貨幣,支付當地的營運開支。於回顧期內,由於董事會認為本集團的外匯風險不高,因此本集團並無運用任何衍生工具以對沖其營運方面的外匯風險。

Capital Expenditure and Contingent Liabilities

During the Period, capital expenditure of the Group was US$123,000 (1H 2025: US$1.8 million).

As at 30 June 2026, there was US$1.7 million capital expenditure contracted but not provided for (31 December 2025: US$2.2 million).

Aside from the aforesaid, the Group had no other material capital commitment or contingent liability.

資本開支與或然負債

2026年上半年期間，本集團的資本開支為123,000美元（2025年上半年：1.8百萬元）。

於2026年6月30日，共有1.7百萬美元已商定合約但未撥備之資本開支（2025年12月31日：2.2百萬美元）。

除前述之外，本集團概無其他重大資本承擔或或然負債。

Acquisition and Disposal of Material Subsidiaries and Associates

The Group did not acquire or dispose of any material subsidiaries and associates during the Period.

收購及出售重大附屬公司及聯營公司

於回顧期內，本集團並無收購或出售任何重大附屬公司及聯營公司。

Charge of Assets

As at 30 June 2026, pledged bank deposits which amounted to US$2.5 million (31 December 2025: US$2.5 million) were pledged to banks to secure against banking facilities.

資產抵押

於2026年6月30日，金額為2.5百萬美元（2025年12月31日：2.5百萬美元）的已抵押銀行存款已抵押予銀行作抵押銀行融資用途。

HUMAN RESOURCES AND REMUNERATION POLICY

As of 30 June 2026, the Group had a total workforce of 279 employees*. About 37% of the workforce were based at the Hong Kong headquarters, with the rest located in China and Taiwan. Employee salaries and other employee benefit expenses increased to US$12.0 million during the Period from US$11.9 million in the first half of 2025, which represented an increase of 0.8%. There was no significant change in the total amount of staff cost and employee benefit expenses. The Group's remuneration policies are formulated on the performance of individual employees, which will be reviewed every year. Apart from the provident fund scheme (according to the provisions of the Mandatory Provident Fund Schemes for Hong Kong employees) or the government-managed retirement pension scheme (for Mainland China and Taiwan employees), medical and other insurance benefits, discretionary bonuses are also awarded to employees according to the assessment of individual performance.

* Data excludes the testing center in Mainland China

人力資源及薪酬制度

於2026年6月30日，本集團共有279名員工*。整體員工中約37%駐香港總辦事處，其餘員工分別駐中國內地及台灣。僱員薪金及其他福利由2025年上半年約11.9百萬美元增加至本期間約12.0百萬美元，增加0.8%，僱員薪金及其他福利總額並無重大變化。本集團的薪酬政策乃按個別僱員表現制定，將每年予以檢討。除公積金計劃（根據適用於香港僱員的強制性公積金條例的條款）及政府管理退休金計劃（適用於中國內地及台灣僱員）、醫療及其他保險外，亦會根據個別僱員表現的評估而向僱員授出酌情花紅。

* 數據不包括於中國內地之測試中心

As at 30 June 2026, the interests and short positions of each Director and the chief executive in the shares and underlying shares of the Company or its associated corporations (within the meaning of the Securities and Futures Ordinance), as recorded in the register required to be kept by the Company under Section 352 of part XV of the SFO or as notified to the Company and the Stock Exchange pursuant to the Model Code for Securities Transactions by Directors of Listed Issuers were as follows:

於2026年6月30日，各董事及行政總裁於本公司及其相聯法團（定義見證券及期貨條例）的股份及相關股份中擁有登記於根據SFO第XV部第352條規定本公司須存置的登記名冊上，或須根據上市發行人董事進行證券交易的標準守則知會本公司及聯交所的權益及淡倉如下：

			Ordinary shares in the Company as at 30 June 2026 於2026年6月30日本公司的普通股			
		Position 權益狀況	Number of shares held 所持股份數目	Number of share options held (i) 所持購股權數目 (i)	Total 總計	% of the issued share capital of the Company 佔本公司已發行股本百分比
Independent Non-executive Directors	**獨立非執行董事**					
Dr. Chan Philip Ching Ho	陳正豪博士	Long position 好倉	–	–	–	–
Mr. Chan Chi Kong	陳志光先生	Long position 好倉	–	–	–	–
Dr. Kwok Hoi Sing	郭海成博士	Long position 好倉	–	–	–	–
Non-executive Directors	**非執行董事**					
Mr. Yang Kun	楊琨先生	Long position 好倉	–	–	–	–
Mr. Xie Shan Shan (appointed with effect from 18 June 2026)	謝彡彡先生（於2026年6月18日獲委任）	Long position 好倉	–	–	–	–
Mr. Wang Hui (resigned on 18 June 2026)	王輝先生（於2026年6月18日辭任）	Long position 好倉	–	–	–	–
Ms. Liu Fei	劉斐女士	Long position 好倉	–	–	–	–
Executive Director	**執行董事**					
Mr. Wang Wah Chi, Raymond	王華志先生	Long position 好倉	5,600,000	–	5,600,000	0.22%

Notes:

(i) Details of share options granted under the 2013 Share Option Scheme are disclosed on pages 50 to 52.

附註：

(i) 該等購股權為根據2013購股權計劃（詳情見第50到52頁）授出之購股權。

Saved as disclosed above, at no time during the Period, did the Directors and chief executive (including their spouse and children under 18 years of age) have any interests in, or had been granted, or exercised, any rights to subscribe for shares of the Company and its associated corporations required to be disclosed pursuant to the SFO.

除上文所披露者外，於期內任何時間，董事及行政總裁（包括彼等之配偶及年齡在18歲以下的子女）概無擁有或獲授予或行使根據SFO須予披露可認購本公司及其相聯法團之股份的任何權利。

Saved as disclosed above, at no time during the Period was the Company, its subsidiaries or its associated corporations a party to any arrangement to enable the Directors and chief executive of the Company (including their spouse and children under 18 years of age) to hold any interests or short positions in the shares or underlying shares in, or debentures of, the Company or its associated corporations.

除上文所披露外，於期內任何時間，概無本公司、其附屬公司或其相聯法團為任何安排的其中一方，讓本公司董事及行政總裁（包括彼等之配偶及年齡在18歲以下的子女）持有本公司或其相聯法團的股份或相關股份或債權證的任何權益或淡倉。

Saved as disclosed above, at no time during the Period had the Directors and chief executive of the Company (nor their associates) any interests in, or been granted, or exercised, any rights to subscribe for shares of the Company or its associated corporations required to be disclosed pursuant to the SFO.

除上文所披露者外，於期內任何時間，本公司董事及行政總裁（及彼等之聯繫人）概無擁有或獲授予或行使根據SFO須予披露可認購本公司及其相聯法團之股份的任何權利。

SUBSTANTIAL SHAREHOLDERS' INTERESTS
主要股東權益

The register of substantial shareholders required to be kept by the Company under section 336 of Part XV of the SFO shows that as at 30 June 2026, the Company had been notified of the following substantial shareholders' interests in the shares of the Company, being interests of 5% or more of the Company's issued share capital. These interests are in addition to those disclosed above in respect of the Directors and the chief executive officer of the Company.

根據SFO第XV部第336條須存置的主要股東登記名冊所示，於2026年6月30日，本公司已獲知會下列主要股東的權益（即於本公司已發行股本擁有5%或以上權益）。該等權益為上文披露的本公司董事及行政總裁權益以外的。

			Ordinary shares in the Company as at 30 June 2026 於2026年6月30日本公司的普通股			
Name of shareholder 股東名稱	**Capacity 身份**	**Position 權益狀況**	**Number of shares held 所持股份數目**	**Number of share options held 所持購股權數目**	**Total 總計**	**% of the issued share capital of the Company 佔本公司已發行股本百分比**
Huada Semiconductor Co., Ltd 華大半導體有限公司	Beneficial owner 實益擁有人	Long position 好倉	706,066,000	–	706,066,000	28.27%
*China Electronics Limited(i) 中國電子有限公司(i)	Interest of controlled corporation 所控制的法團的權益	Long position 好倉	706,066,000	–	706,066,000	28.27%
*China Electronics Corporation(i) 中國電子信息產業集團有限公司(i)	Interest of controlled corporation 所控制的法團的權益	Long position 好倉	706,066,000	–	706,066,000	28.27%

Note:

(i) Huada Semiconductor Co., Ltd. is 58.07% owned by China Electronics Limited, and China Electronics Limited is 81.66% owned by China Electronics Corporation ("CEC"). CEC is a state-owned information technology conglomerate under the administration of the central government of the People's Republic of China.

* English name is for identification purposes only

附註：

(i) 中國電子有限公司持有華大半導體有限公司58.07%股權，而中國電子信息產業集團有限公司(「中國電子」)持有中國電子有限公司81.66%股權。中國電子為一家直接隸屬於中華人民共和國中央政府管理的國有電子信息技術企業集團。

* 英文名稱僅供識別之用

Saved as disclosed above, as at 30 June 2026, no other persons (other than the Directors) were recorded in the register of the Company required to be kept under Section 336 of the SFO as having interests or short positions in the shares and underlying shares of the Company.

除上文所披露者外，於2026年6月30日，根據SFO第336條本公司須予備存的登記冊所記錄，概無其他人士(董事除外)擁有本公司股份及相關股份的權益或淡倉。

The Company adopted a share option scheme (the "2013 Share Option Scheme") at the annual general meeting held on 28 May 2013. The terms of the 2013 Share Option Scheme are in accordance with the provisions of Chapter 17 of the Listing Rules. The 2013 Share Option Scheme is valid and effective for a period of 10 years commencing on 28 May 2013, being the date of adoption of such scheme by the shareholders of the Company. The Board shall be entitled at any time within 10 years commencing on 28 May 2013 to make an offer for the grant of an option to any qualifying participants.

本公司於2013年5月28日舉行的股東週年大會已採納一購股權計劃(「2013購股權計劃」)。2013購股權計劃的條款是遵照上市規則第17章的條文。2013購股權計劃由2013年5月28日(即本公司股東採納該購股權計劃之日)起生效,為期10年。董事會可以於2013年5月28日起10年內授出購股權予合資格參與者。

The purpose of the 2013 Share Option Scheme is to provide the participants (directors, employees, advisers, consultants, agents, distributors, contractors, contract manufacturers, suppliers, service providers, customers, business partners, joint venture business partners, etc., of any member of the Group) with the opportunity to acquire proprietary interests in the Company and to encourage them to work towards enhancing the value of the Company for the benefit of the Company and its shareholders as a whole.

2013購股權計劃旨在給予合資格參與者(本集團成員之董事、員工、顧問、諮詢、代理、分銷商、承包商、承包製造商、供應商、服務提供者、客戶、商業夥伴、合營企業商業夥伴等)機會獲得本公司專有股份和鼓勵共同合作為本公司及其股東整體利益而提升本公司價值。

The total number of shares which may be issued upon exercise of all options to be granted under the 2013 Share Option Scheme must not in aggregate exceed 10% of the issued share capital of the Company at the date of approval of the 2013 Share Option Scheme or 30% of the issued share capital of the Company from time to time.

根據2013購股權計劃所授出的所有購股權獲行使而可予發行的股份總數,不得超過於批准購股權計劃當日本公司已發行股本10%或本公司不時已發行股本30%。

The total number of shares of the Company issued and to be issued upon exercise of the options granted to each participant (including exercised, cancelled and outstanding options) in any 12-month Period shall not exceed 1% of the shares of the Company in issue.

每名參與者在任何12個月內獲授的購股權(包括已行使、註銷或尚未行使)獲行使時已經及即將發行的本公司股份總數,合計不得超過本公司已發行股份的1%。

An offer shall remain open for acceptance by the qualifying participant concerned for a Period of 21 days from the date of the offer (or such longer Period as the Board may specify in writing). HK$1.00 is payable by the grantee to the Company on acceptance of the offer of the option.

購股權於建議日期起計21日期間(或董事會可書面訂明的較長期間)內可供合資格參與者接納。於接納購股權時,承授人須向本公司支付港幣1.00元。

The subscription price of share option shall be determined by the Board at its absolute discretion in accordance with the terms of the 2013 Share Option Scheme. The subscription price in respect of any particular option shall be no less than the higher of (a) the closing price of the Shares as stated in the daily quotations sheet issued by the Stock Exchange on the date of grant; and (b) the average closing price of the Shares as stated in the daily quotations sheets issued by the Stock Exchange for the five business days immediately preceding the date of grant.

在2013購股權計劃條文規定下，董事會具有絕對權力訂立購股權的認購價。任何個別購股權的認購價須為以下的較高者：(a)股份於授出日期在聯交所每日報價表所列收市價；及(b)股份在緊接授出日期前5個營業日在聯交所每日報價表所列平均收市價。

Given that the 2013 Share Option Scheme expired on 27 May 2023, no share option was granted during the Period, and the number of share options available for grant under the scheme mandate limit as of 1 January 2026 and 30 June 2026 was nil and nil, respectively.

因2013購股權計劃已於2023年5月27日屆滿，於回顧期內並無授出購股權，以及於2026年1月1日及2026年6月30日換股權計劃下授權可予發行的購股權數目分別為零。

The number of share options outstanding as at 30 June 2026 was 250,000, with rights to subscribe for 250,000 shares of the Company, representing 0.01% of the total number of issued shares of the Company.

於2026年6月30日，合共有250,000股有效購股權未經行使，有權認購本公司250,000股股份，佔本公司已發行股份總數的0.01%。

Details of the share options outstanding as at 30 June 2026 under the 2013 Share Option Scheme are as follows:

於2026年6月30日關於2013購股權計劃授出之購股權的詳情如下：

Name of Directors 董事名稱	Unaudited 未經審核 Number of share options (in thousand units) 購股權數目(以千位計) Held on 1 January 2026 於2026年1月1日持有	Granted during the period 期內已授出	Exercised during the period 期內已行使	Lapsed/forfeited during the period 期內已註銷／放棄	Held on 30 June 2026 於2026年6月30日持有	Exercise price for the share options granted per share HK$ 每股購股權授出之行使價 港元	*Share price of the Company immediately before the exercise/grant date of share options (note) HK$ *緊接購股權行使／授出日期之前本公司股價(附註) 港元	Grant date 授出日期	Vesting period 歸屬期／日	Exercise period 行使期
Senior management & others 高級管理層及其他	250	-	-	(250)	-	0.546	NA 不適用/0.500	24 March 2023 2023年3月24日	24 March 2023 to 24 March 2024 由2023年3月24日至2024年3月24日	From 25 March 2024 to 24 March 2026 由2024年3月25日至2026年3月24日
	250	-	-	-	250	0.546	NA 不適用/0.500	24 March 2023 2023年3月24日	24 March 2023 to 24 March 2025 由2023年3月24日至2025年3月24日	From 25 March 2025 to 24 March 2027 由2025年3月25日至2027年3月24日
Subtotal 小計	500	-	-	(250)	250					
Total 總計	500	-	-	(250)	250					

* The weighted average share closing price of the shares immediately before the date on which the options were exercised or the closing price of the shares immediately before the dates on which the options were granted (as applicable)

* 緊接購股權行使日之前的股份加權平均收市價或緊接購股權行使日之前的股份收市價(視情況而定)

Compliance with Corporate Governance Code

The Board and the management of the Group are committed to achieving and maintaining high standards of corporate governance, which the Group considers as critical in safeguarding the integrity of its business operations and maintaining investors' trust in the Company.

The Company has complied with all the applicable Code Provisions in the Corporate Governance Code as set out in Appendix C1 to the Listing Rules throughout the six months ended 30 June 2026.

遵守企業管治守則

董事會及本集團的管理層承諾達到及保持高水平的企業管治，這也是維護業務營運的誠信和保持投資者對本公司信心的關鍵因素。

截至2026年6月30日止6個月期間，本公司一直遵守上市規則附錄C1所載之企業管治守則中所有適用的守則條文。

Compliance with the Model Code

The Company has its own written guidelines on securities transactions by Directors and relevant employees on terms no less exacting than the required standard set out in Appendix C3 to the Listing Rules. Specific enquiry has been made to all Directors, and all Directors have confirmed that they have been in compliance with such guidelines during the six months ended 30 June 2026. In addition, during the six months ended 30 June 2026, the Company was not aware of any non-compliance with the Model Code by the relevant employees of the Group.

遵守標準守則

本公司備有就董事及有關員工進行的證券交易的書面指引，條款與上市規則附錄C3所載的規定標準同樣嚴格。本公司已向全體董事作出具體查詢，於截至2026年6月30日止6個月期間，彼等均一直遵守該等指引。此外，本公司未獲悉本集團相關僱員於截至2026年6月30日止6個月期間有任何不遵守標準守則之情況。

Purchase, Sale or Redemption of the Company's Listed Shares

There was no purchase, sale or redemption of the Company's listed shares by the Company or any of its subsidiaries during the six months ended 30 June 2026.

購買、出售或贖回本公司上市股份

於截至2026年6月30日止6個月期間，本公司或其任何附屬公司並無購買、出售或贖回本公司上市股份。

Review of Interim Condensed Consolidated Financial Information

The Audit Committee is composed of two Independent Non-executive Directors and one Non-executive Director. The unaudited interim condensed consolidated financial information has been reviewed by the Audit Committee of the Company alongside the management.

The unaudited interim condensed consolidated financial information has been reviewed by the Company's independent auditor, Ernst & Young, in accordance with Hong Kong Standard on Review Engagements 2410 "Review of Interim Financial Information Performed by the Independent Auditor of the Entity" issued by the Hong Kong Institute of Certified Public Accountants. The auditor's independent review report is included in the Interim Report of the Company.

審閱中期簡明綜合財務資料

審核委員會由2名獨立非執行董事及1名非執行董事組成。未經審核的中期簡明綜合財務資料，已通過管理層聯同審核委員會審閱。

該等未經審核的中期簡明綜合財務資料，已經由本公司獨立核數師安永會計師事務所根據香港會計師公會頒佈的香港審閱準則第2410號「由實體的獨立核數師執行中期財務資料審閱」進行審閱。核數師的獨立審閱報告載於本公司中期報告內。

Investor Relations and Communications

The Group recognizes the rights of the Company's shareholders to know more about its business and prospects, and therefore it has always taken a proactive approach to communicate with the investment community, for example, institutional investors, sell-side analysts and retail investors. During the Period, the Group held conference calls with investors and analysts. Stakeholders of the Company are recommended to visit the Group's website (*www.solomon-systech.com*) from time to time, where up-to-date information of the Group can be accessed.

投資者關係及溝通

本集團深明本公司股東有權對本集團業務及前景有更多了解，故此本集團一直採取積極態度與投資大眾(例如：機構投資者、賣方分析員及散戶投資者)溝通。於2026上半年，本集團繼續與投資者及分析員舉行電話會議。本集團建議權益人不時登入本集團網站(*www.solomon-systech.com*)，查閱本集團的最新資訊。

Publication of Interim Results on the Stock Exchange's Website and the Company's Website

All the interim financial and other related information of the Group required by the Listing Rules has been published on the Stock Exchange's website (*www.hkexnews.hk*) and the Company's website (*www.solomon-systech.com*) on 21 August 2026.

中期業績於聯交所網站及本公司網站公佈

本公司已於2026年8月21日於聯交所網站(*www.hkexnews.hk*)及本公司網站(*www.solomon-systech.com*)公佈所有根據上市規則規定的本集團的中期財務及相關資料。

On behalf of the Board
Solomon Systech (International) Limited
WANG Wah Chi, Raymond
Chief Executive Officer

Hong Kong, 21 August 2026

代表董事會
晶門半導體有限公司
王華志
行政總裁

香港，2026年8月21日

DEFINITIONS AND GLOSSARY

Board	Board of Directors
CEACI	CEAC International Limited, a company incorporated in Hong Kong with limited liability and a wholly-owned subsidiary of CECI, and a connected person of the Company
CEC	China Electronics Corporation, a state-owned information technology conglomerate under the administration of the central government of the PRC, is a substantial shareholder of the Company through its interests in Huada
CECI	深圳中電國際信息科技有限公司 (CECI Technology Co., Ltd.*), a company established in the PRC and an indirect subsidiary of the CEC, and a connected person of the Company
China/Mainland China	The People's Republic of China excluding, for the purpose of this report, the Hong Kong Special Administrative Region, the Macau Special Administrative Region and Taiwan
Code Provision(s)	Code provision(s) in the Corporate Governance Code contained in Appendix C1 to the Listing Rules
Company	Solomon Systech (International) Limited, a company incorporated in the Cayman Islands with limited liability, the shares of which are listed on the Main Board of the Stock Exchange
Debt to equity ratio	Interest-bearing bank borrowing divided by total equity
Director(s)	The director(s) of the Company
ESL	Electronic Shelf Label
Group	The Company and its subsidiaries
HKAS	Hong Kong Accounting Standards
HK$/HKD	Hong Kong dollars
Hong Kong/HK/HKSAR	Hong Kong Special Administrative Region
Huada	Huada Semiconductors Co. Ltd., a PRC company with limited liability to consolidate all IC businesses under CEC group. It is a substantial shareholder of the Company
IC	Integrated Circuit
LCD	Liquid Crystal Display
Listing Rules	The Rules Governing the Listing of Securities on the Stock Exchange
MIPI	Mobile Industry Processor Interface
Model Code	Model Code for Securities Transactions by Directors of Listed Issuers contained in Appendix C3 to the Listing Rules
OLED	Organic Light Emitting Diode
PMOLED	Passive Matrix Organic Light Emitting Diode
R&D	Product design, development and engineering
S&D	Selling and Distribution
SFO	Securities and Futures Ordinance
the Stock Exchange	The Stock Exchange of Hong Kong Limited
TDDI	Touch and Display Driver Integration
TFT	Thin Film Transistor
UK	United Kingdom
USA/US/United States	United States of America
US$	US dollars

* for identification purpose only

釋義及詞彙

董事會	董事會
CEACI	中國電子器材國際有限公司，於香港註冊成立之有限公司，為CECI的全資附屬公司
中國電子	中國電子信息產業集團有限公司，一家直接隸屬於中國中央政府管理的國有電子信息技術企業集團，通過控制華大的權益為本公司主要股東
CECI	深圳中電國際信息科技有限公司，於中國註冊成立之有限責任公司，為中國電子集團之間接附屬公司
中國／中國內地	中華人民共和國，就本報告而言，不包括香港特別行政區、澳門特別行政區及台灣
守則條文	上市規則附錄C1所載之企業管治守則中的守則條文
本公司	晶門半導體有限公司，一家成立於開曼群島的有限公司，其股份於聯交所主板上市
債務權益比率	銀行計息貸款除以總權益
董事	本公司之董事
電子貨架標籤	電子貨架標籤
本集團	本公司及其附屬公司
香港會計準則	香港會計準則
港元	香港元
香港	香港特別行政區
華大	華大半導體有限公司，一家CEC為整合旗下IC企業而組建於中國的有限公司，乃本公司之主要股東
IC	集成電路晶片
LCD	液晶顯示器
上市規則	聯交所證券上市規則
MIPI	移動行業處理器界面
標準守則	上市規則附錄C3所載之上市發行人董事進行證券交易的標準守則
OLED	有機發光二極體
PMOLED	無源矩陣有機發光二極體
工程研發	產品設計、開發及工程
銷售及分銷	銷售及分銷
SFO	證券及期貨條例
聯交所	香港聯合交易所有限公司
TDDI	觸控與顯示驅動器集成
TFT	薄膜電晶體
英國	大英聯合王國
美國	美利堅合眾國
美元	美國元

CORPORATE AND SHAREHOLDER INFORMATION
公司及股東資料

Financial Calendar

Financial Year End
31 December

Announcement of Interim Results
21 August 2026

Share Listing

Listing Venue and Date
Main Board of The Stock Exchange of Hong Kong Limited
8 April 2004

HKSE Stock Code
2878

Board Lot
2,000 shares

Trading Currency
HKD

Issued Shares
2,497,752,351 (as at 30 June 2026)

Principal Share Registrar and Transfer Agent

Vistra (Cayman) Limited
P. O. Box 31119
Grand Pavilion, Hibiscus Way,
802 West Bay Road,
Grand Cayman
KY1-1205
Cayman Islands

財務日誌

財政年度結算日
12月31日

公佈中期業績
2026年8月21日

股份上市資料

上市地點及日期
香港聯合交易所有限公司主板
2004年4月8日

香港股份編號
2878

買賣單位
2,000股

交易貨幣
港元

已發行股份
2,497,752,351（於2026年6月30日）

股份過戶登記總處

Vistra (Cayman) Limited
P. O. Box 31119
Grand Pavilion, Hibiscus Way,
802 West Bay Road,
Grand Cayman
KY1-1205
Cayman Islands

Hong Kong Branch Share Registrar

Tricor Investor Services Limited
17/F, Far East Finance Centre
16 Harcourt Road
Hong Kong
Tel: (852) 2980 1333
Fax: (852) 2810 8185
Website: *www.tricoris.com*

香港股份過戶登記分處

卓佳證券登記有限公司
香港
夏慤道16號
遠東金融中心17樓
電話：(852) 2980 1333
傳真：(852) 2810 8185
網址：*www.tricoris.com*

Independent Auditor

Ernst & Young
Certified Public Accountants
Registered Public Interest Entity Auditor
27/F, One Taikoo Place
979 King's Road
Quarry Bay, Hong Kong

獨立核數師

安永會計師事務所
執業會計師
註冊公眾利益實體核數師
香港鰂魚涌
英皇道979號
太古坊一座27樓

Solicitors

Loeb & Loeb LLP

法律顧問

樂博律師事務所有限法律責任合夥

Board Members

Executive Director

Mr. Wang Wah Chi, Raymond *(Chief Executive Officer)*

Non-executive Directors

Mr. Yang Kun *(Chairman)*
Mr. Xie Shan Shan
(appointed with effect from 18 June 2026)
Mr. Wang Hui (resigned on 18 June 2026)
Ms. Liu Fei

董事成員

執行董事

王華志先生*(行政總裁)*

非執行董事

楊琨先生*(主席)*
謝釤釤先生
(於2026年6月18日獲委任)
王輝先生(於2026年6月18日辭任)
劉斐女士

Independent Non-executive Directors

Mr. Chan Chi Kong
Dr. Chan Philip Ching Ho
Dr. Kwok Hoi Sing

獨立非執行董事

陳志光先生
陳正豪博士
郭海成博士

Authorized Representatives

Mr. Wang Wah Chi, Raymond
Mr. Yu Chon Man

授權代表

王華志先生
余俊敏先生

Company Secretary & Qualified Accountant

Mr. Yu Chon Man
CPA, FCCA

公司秘書及合資格會計師

余俊敏先生
CPA, FCCA

Corporate Communications/Investor Relations

Email: *ir@solomon-systech.com*

企業傳訊╱投資者關係

電郵：*ir@solomon-systech.com*

Principal Office

Unit 607-613, 6/F. Wireless Centre
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Shatin, New Territories
Hong Kong
Tel: (852) 2207 1111
Fax: (852) 2267 0800

總辦事處

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新界沙田
香港科學園
科技大道東3號無線電中心
6樓607-613室
電話：(852) 2207 1111
傳真：(852) 2267 0800

Website

www.solomon-systech.com

網址

www.solomon-systech.com

This 2026 Interim Report (bilingual version in English and Chinese) has been posted on the Company's website at www.solomon-systech.com.

本2026年中期報告的中英文雙語合併本已登載於本公司網站www.solomon-systech.com。

Shareholders who have chosen to receive the Company's corporate communications (including but not limited to annual reports, summary financial reports (where applicable), interim reports, summary interim reports (where applicable), notices of meeting, listing documents, circulars and proxy forms) via the Company's website and for any reason have difficulty in gaining access to the Interim Report posted on the Company's website will promptly upon request be sent by post the Interim Report in printed form free of charge.

選擇透過本公司網站收取本公司的公司通訊(其中包括但不限於年報、財務摘要報告(如適用)、中期報告、中期摘要報告(如適用)、會議通告、上市文件、通函及代表委任表格),及因任何理由以致在接收載於本公司網站的中期報告上出現困難的股東,可即時要求以郵寄方式獲免費發送中期報告的印刷本。

Shareholders may at any time change their choice of means of receipt of the Company's corporate communications

股東可隨時更改收取本公司的公司通訊方式

Shareholders may request for printed copy of the Interim Report or change their choice of means of receipt of the Corporate Communications by sending reasonable notice in writing to the Company's branch share registrar in Hong Kong, Tricor Investor Services Limited, at 17/F, Far East Finance Centre, 16 Harcourt Road, Hong Kong or by sending an email to solomon2878-ecom@hk.tricorglobal.com.

股東可在給予本公司合理時間的書面通知,要求索取中期報告的印刷本或更改收取本公司之公司通訊的方式,該書面通知應交予本公司之香港股份過戶登記分處—卓佳證券登記有限公司,地址為香港夏慤道16號遠東金融中心17樓,或將該通知電郵至solomon2878-ecom@hk.tricorglobal.com。

www.solomon-systech.com

Solomon Systech (International) Limited
晶門半導體有限公司

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